

# Compal Confidential

## VIUS5 LA-9001P M/B Schematics Document

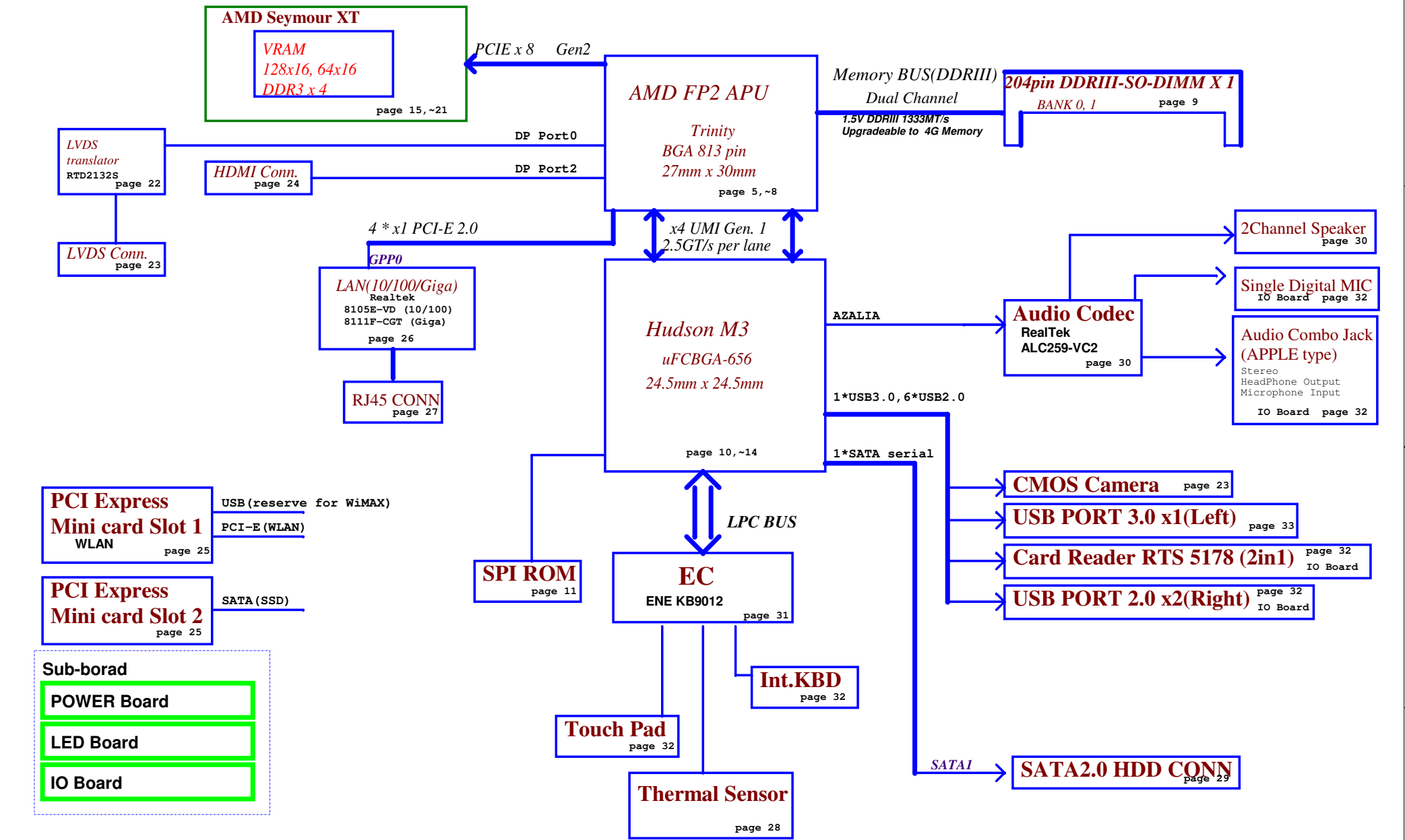
AMD FP2 Processor with DDRIII + Husdon M3 FCH

AMD VGA Seymour XT

2012-05-31

REV : 0 . 3

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<div>power plane</div> <div>State</div>	+B	+5VALW  +3VALW  +1.1VALW	+1.5V  +1.5V_APU	<div>+5VS</div> <div>+3VS</div> <div>+2.5VS</div> <div>+1.5VS</div> <div>+1.2VS</div> <div>+1.1VS</div> <div>+0.75VS</div> <div>+APU_CORE</div> <div>+APU_CORE_NB</div> <div>+VGA_CORE</div> <div>+3.3VGS</div> <div>+1.8VGS</div> <div>+1.5VGS</div> <div>+1.0VGS</div>
S0	O	O	O	O
S3	O	O	O	X
S5 S4/AC	O	O	X	X
S5 S4/ Battery only	O	X	X	X
S5 S4/AC & Battery don't exist	X	X	X	X

<i>STATE</i> \ <i>SIGNAL</i>	<i>SLP_S3#</i>	<i>SLP_S5#</i>	<i>+VALW</i>	<i>+V</i>	<i>+VS</i>	<i>Clock</i>
<i>Full ON</i>	<i>HIGH</i>	<i>HIGH</i>	<i>ON</i>	<i>ON</i>	<i>ON</i>	<i>ON</i>
<i>S1 (Power On Suspend)</i>	<i>HIGH</i>	<i>HIGH</i>	<i>ON</i>	<i>ON</i>	<i>ON</i>	<i>LOW</i>
<i>S3 (Suspend to RAM)</i>	<i>HIGH</i>	<i>HIGH</i>	<i>ON</i>	<i>ON</i>	<i>OFF</i>	<i>OFF</i>
<i>S4 (Suspend to Disk)</i>	<i>LOW</i>	<i>HIGH</i>	<i>ON</i>	<i>OFF</i>	<i>OFF</i>	<i>OFF</i>
<i>S5 (Soft OFF)</i>	<i>LOW</i>	<i>LOW</i>	<i>ON</i>	<i>OFF</i>	<i>OFF</i>	<i>OFF</i>

Board ID	PCB Revision
0	
1	0.3
2	
3	
4	
5	
6	
7	

ID	BRD ID	Ra	Rb	Vab
0	R10 MP	x	0	0V
1	R03 PVT	100K	8.2K	0.25V
2	R02 DVT	100K	18K	0.5V
3	R01 EVT	100K	33K	0.82V

```
Ra = R1562
Rb = R1564
```

	SOURCE	VGA	BATT	KB9012	SODIMM	WLAN WWAN	Thermal Sensor	FCH	APU	RTD2132
SMB_EC_CK1 SMB_EC_DA1	KB9012 +3VALW	X	V +3VALW	X	X	X	X	X	X	X
SMB_EC_CK2_SUS SMB_EC_DA2_SUS	KB9012 +3VALW	X	X	X	X	X	X	X	V +1.5V	X
FCH_SCLK0 FCH_SDATA0	FCH +3VS	X	X	X	V +3VS	V +3VS	X	X	X	X
SMB_EC_CK2 SMB_EC_DA2	KB9012 +3VS (LV shifter)	V	X	X	X	X	V	X	X	V

Device	Address	Device	Address
Smart Battery	0001_011X b	Thermal Sensor	1001_101xb
		SB-TS (default)	1001_100xb
		VGA(thermal)	1000_001xb
		RTD2132S	1010_1000b

Device	Address
DDR DIMM1	1001 000Xb

USB 2.0	USB 3.0	Port	4 External USB Port	
		0	USB Port (Right Side 1)	
		1	USB Port (Right Side 2)	
		2	Mini Card(WLAN)	
		3	Camera	
		4		
		5	CardReader	
		6		
		7		
		8		
		9		
	XHCI	0	10 USB Port (Left Side)	
		1	11	
		2	12	
		3	13	

OC#	USB Port	
0	USB20 port10	USB30 port0
1	USB20 port0 port1	
2		
3		

Port	Device
1	LAN
2	WLAN
3	
4	

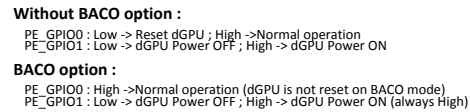
Port	Device
1	
2	
3	
4	

BOM Structure	BTO Item
A4R1@	A4 BGA APU (R1 compal part)
A4R3@	A4 BGA APU (R3 compal part)
A6R1@	A6 BGA APU (R1 compal part)
A6R3@	A6 BGA APU (R3 compal part)
A8R1@	A8 BGA APU (R1 compal part)
A8R3@	A8 BGA APU (R3 compal part)
A10R1@	A10 BGA APU (R1 compal part)
A10R3@	A10 BGA APU (R3 compal part)
SXTR1@	Seymour XT GPU (R1 compal part)
SXTR3@	Seymour XT GPU (R3 compal part)
A70MR1@	A70 Hudson M3 FCH (R1 compal part)
A70MR3@	A70 Hudson M3 FCH (R3 compal part)
PX@	Common VGA circuit
CMOS@	CMOS Camera part
UMA@	UMA strap pin
GAS@	Gastube
8105@	RTL8105E
GIGA@	RTL8111F
HDMI@	HDMI part
NONAOAC@	No AOAC function
AOAC@	support AOAC function
ME@	ME part
DEBUG@	Debug Switch (MP will remove)
@	Unpop
SSD@	SSD part

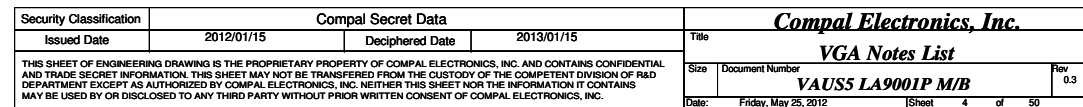
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"Thames" has the following requirements with regards to power-supply sequencing to avoid damaging the ASIC:

- All the ASIC supplies, except for VDDR3, must fully reach their respective nominal voltages within 20 ms of the start of the ramp-up sequence, though a shorter ramp-up duration is preferred. There is no timing requirement on the ramp up of VDDR3 relative to other power rails.
- The external pull-up resistors on the DDC/AUX signals (if applicable) should ramp up before or after both VDDC and VDD\_CT have ramped up.
- VDDC and VDD\_CT should not ramp up simultaneously. For example, VDDC should reach 90% before VDD\_CT starts to ramp up (or vice versa). For BACO enabled designs, VDDC must ramp up before VDD\_CT at system power up.
- For power down, reversing the ramp-up sequence is recommended

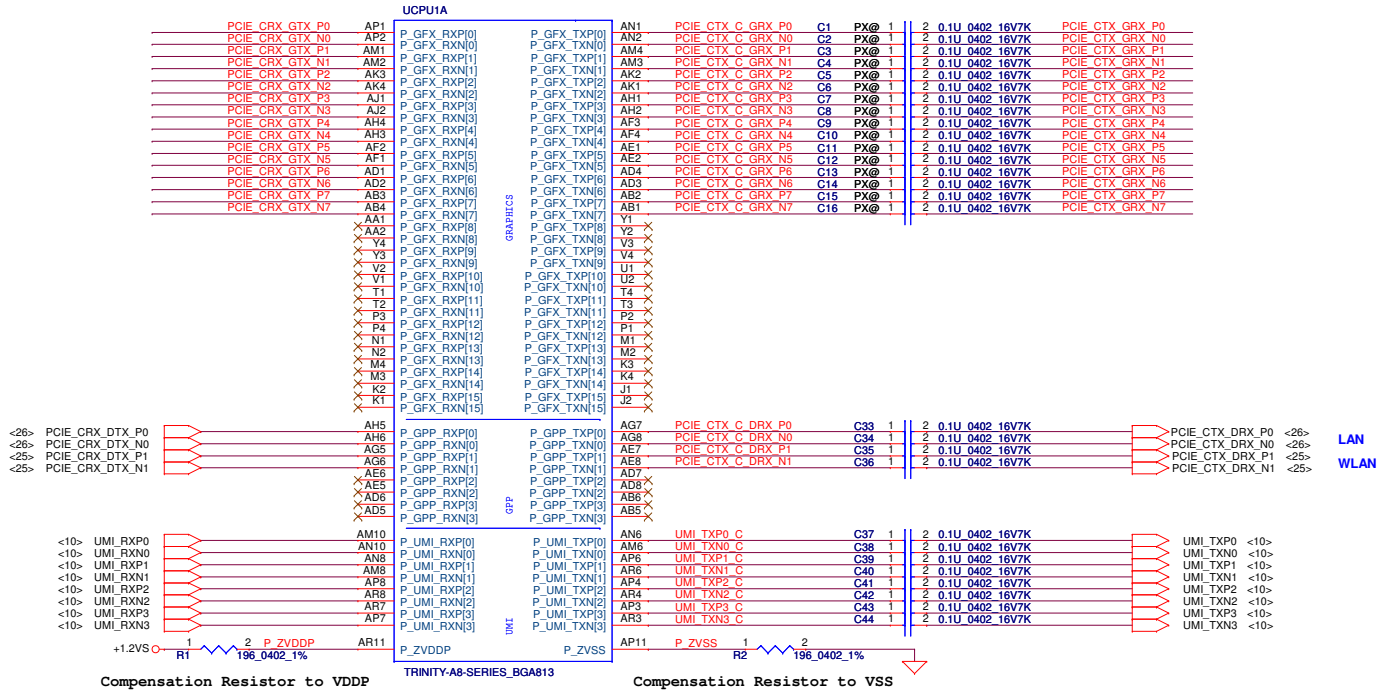


# PX5.0



<15> PCIE\_CRX\_GTX\_P[0..7]  
<15> PCIE\_CRX\_GTX\_N[0..7]

PCIE\_CTX\_GRX\_P[0..7] <15>  
PCIE\_CTX\_GRX\_N[0..7] <15>

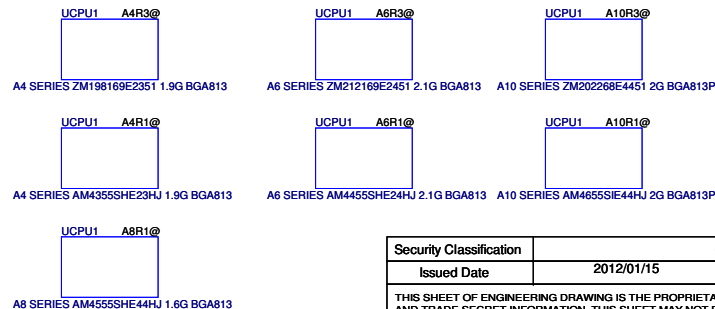
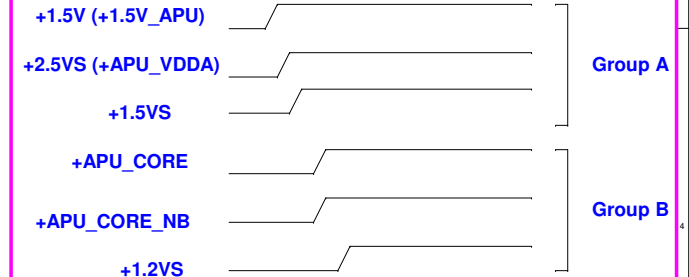


All power supplies in Power Sequencing Group A must be stable and within specification before any power supply in Power Sequencing Group B is greater than 10 percent of its specified typical operating value.

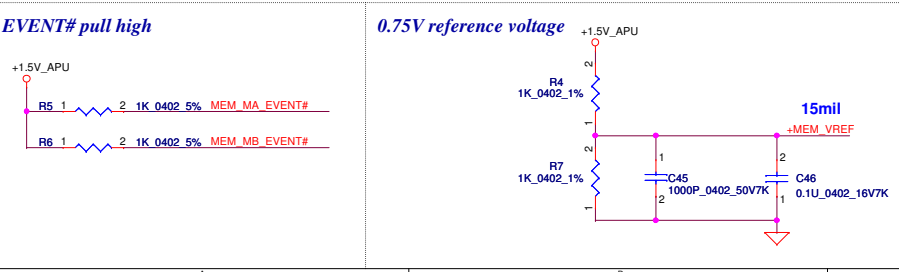
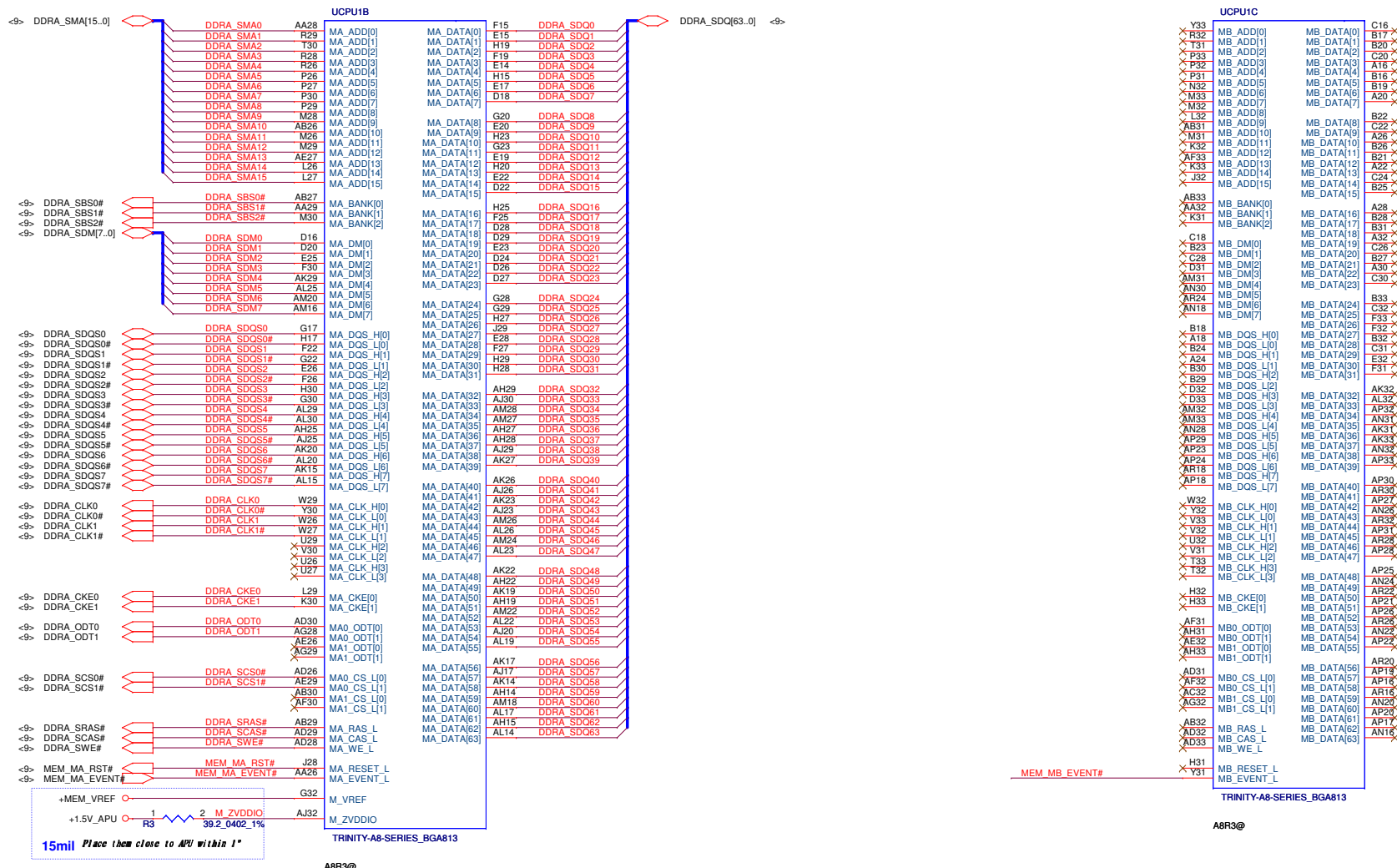
All power supplies in Power Sequencing Group B must be stable and within specification one ms before the assertion of PWR0K.

No sequencing relationships are required between the power sequencing groups during S3 entry. DDR3 compatible processors require VDDIO to remain powered and within specification during the S3 sleep state. All other processor power supply planes are powered down during S3.

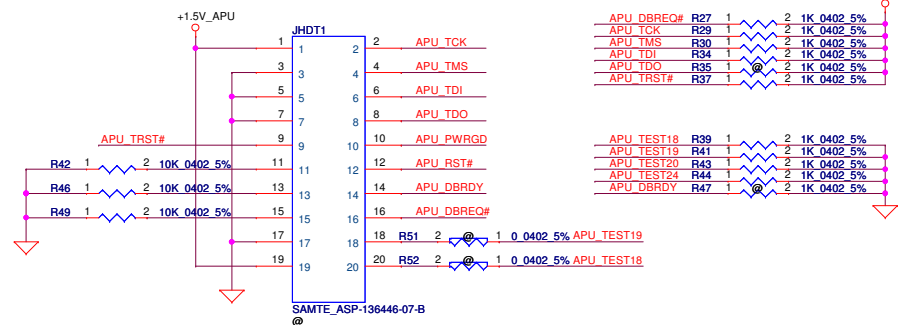
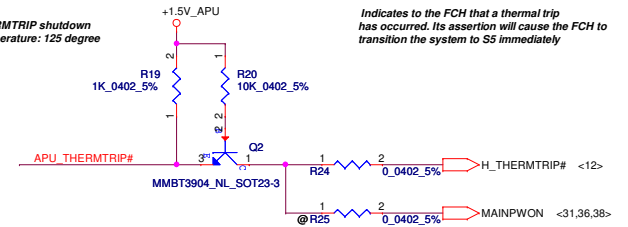
### Power Sequence of APU



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						FP2 DDRIII Memory I/F	0.3
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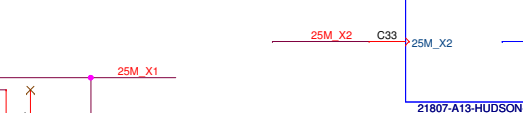
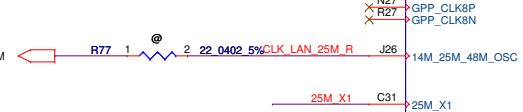
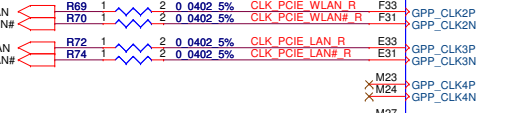
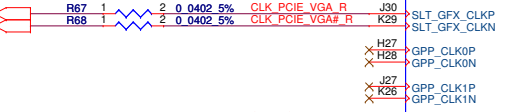
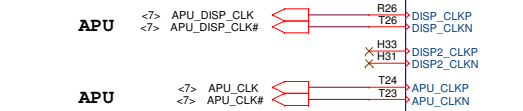
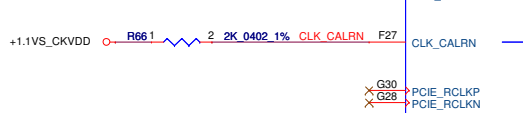
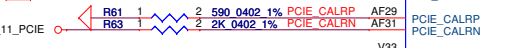
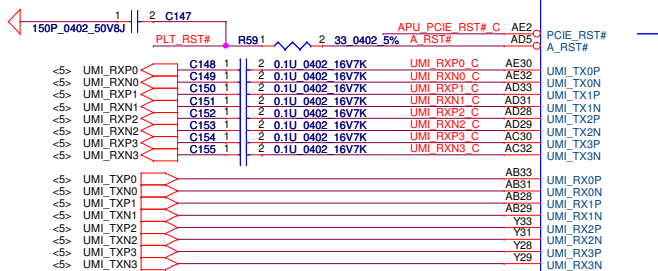




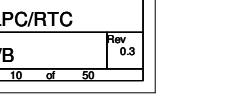
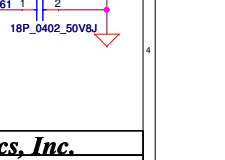
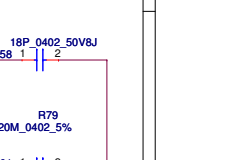
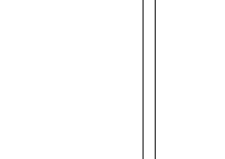
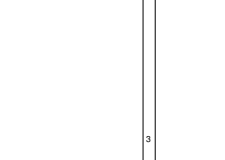
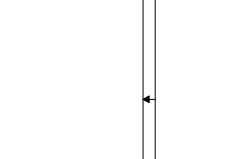
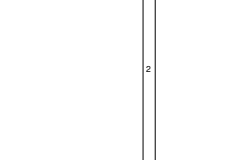
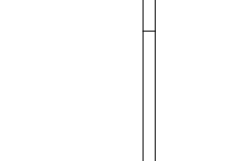
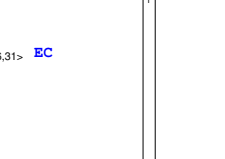
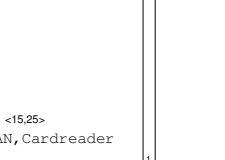
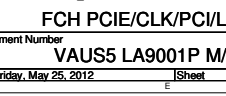
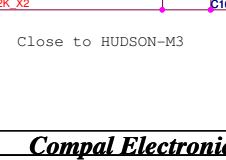
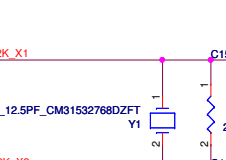
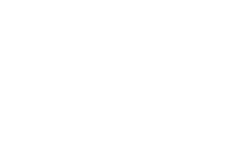
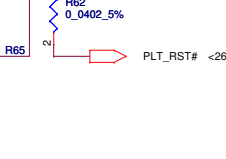
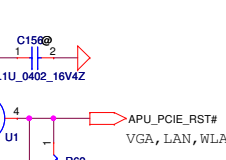
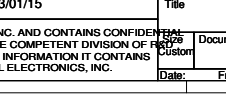
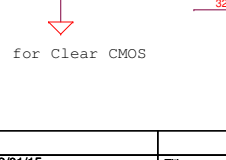
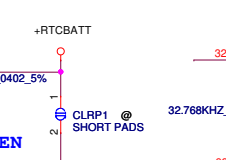
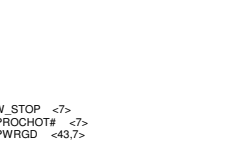
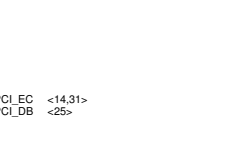
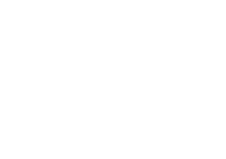
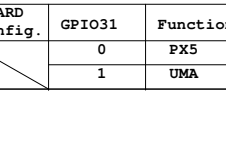
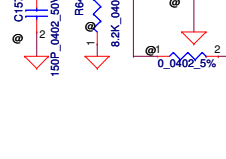
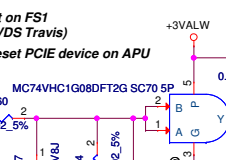
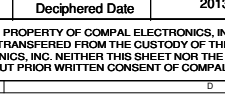
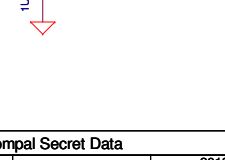
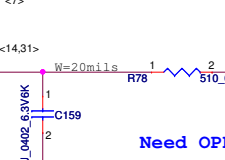
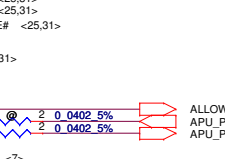
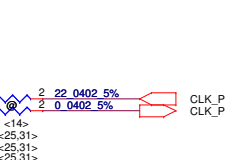
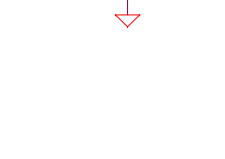
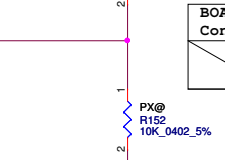
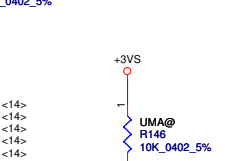
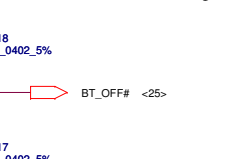
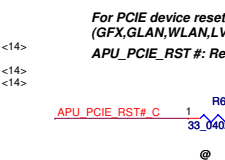
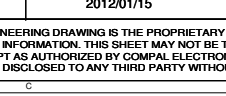
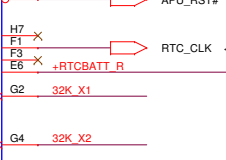
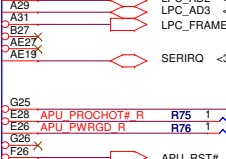
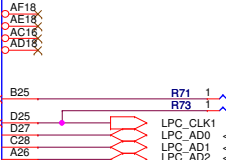
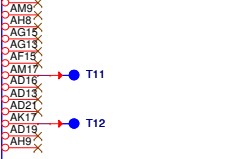
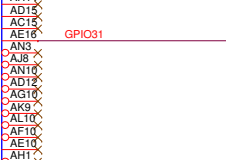
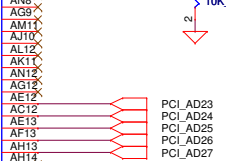
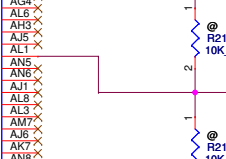
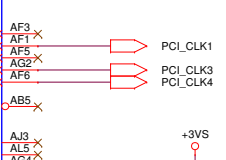
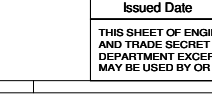
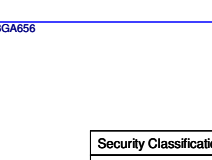
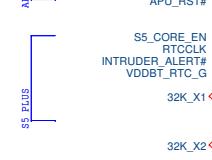
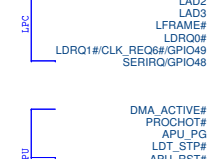
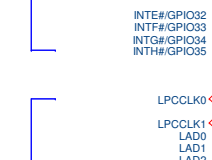
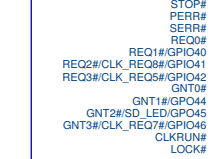
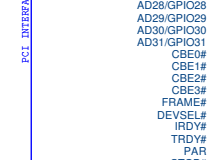
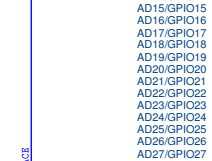
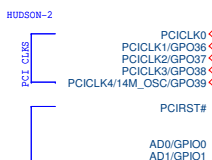


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				VAU55 LA9001P M/B	0.3
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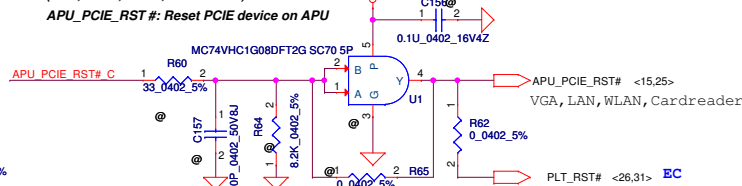
## R59/ C147 close to FCH



## U2A



For PCIE device reset on FS1  
(GFX, GLAN, WLAN, LVDS Travis)  
APU\_PCIE\_RST#: Reset PCIE device on APU



BOARD Config.	GPIO31	Function
0	0	PX5
1	1	UMA

CLK\_PCIE\_EC <14,31>  
CLK\_PCIE\_DB <25>

CLK\_PCIE\_EC <14,31>  
CLK\_PCIE\_DB <25>

CLK\_PCIE\_EC <14,31>  
CLK\_PCIE\_DB <25>

CLK\_PCIE\_EC <14,31>  
CLK\_PCIE\_DB <25>

CLK\_PCIE\_EC <14,31>  
CLK\_PCIE\_DB <25>

CLK\_PCIE\_EC <14,31>  
CLK\_PCIE\_DB <25>

CLK\_PCIE\_EC <14,31>  
CLK\_PCIE\_DB <25>

CLK\_PCIE\_EC <14,31>  
CLK\_PCIE\_DB <25>

CLK\_PCIE\_EC <14,31>  
CLK\_PCIE\_DB <25>

CLK\_PCIE\_EC <14,31>  
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CLK\_PCIE\_EC <14,31>  
CLK\_PCIE\_DB <25>

CLK\_PCIE\_EC <14,31>  
CLK\_PCIE\_DB <25>

CLK\_PCIE\_EC <14,31>  
CLK\_PCIE\_DB <25>

CLK\_PCIE\_EC <14,31>  
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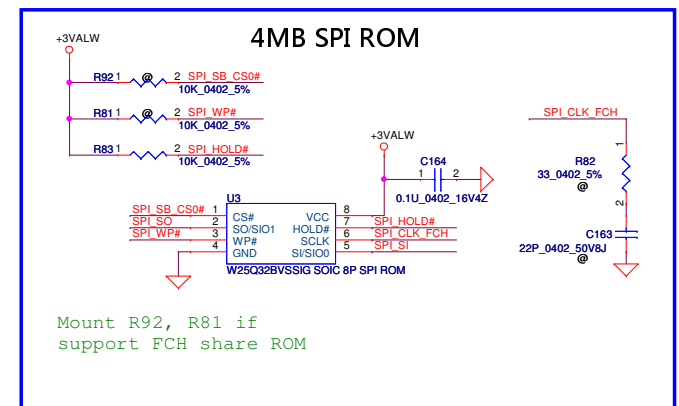
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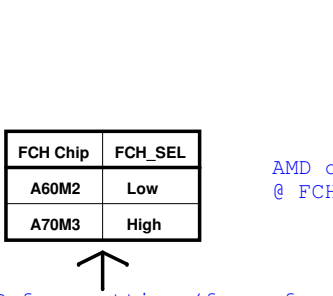
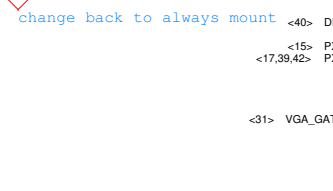
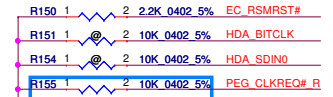
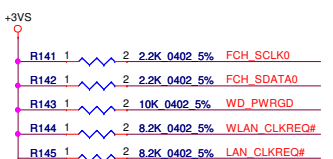
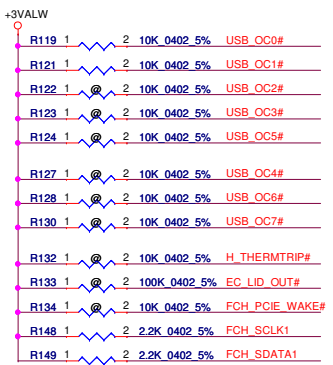
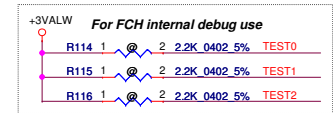
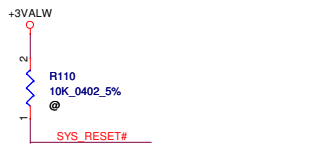
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CLK\_PCIE\_DB <25>

CLK\_PCIE\_EC <14,31>  
CLK\_PCIE\_DB <25>

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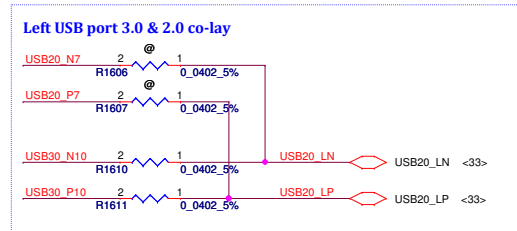
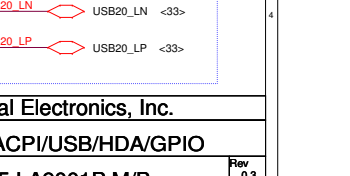
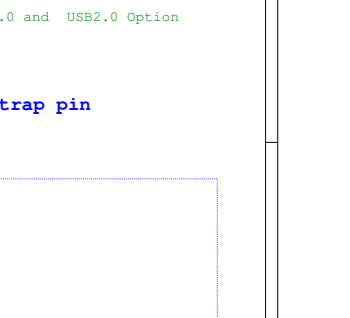
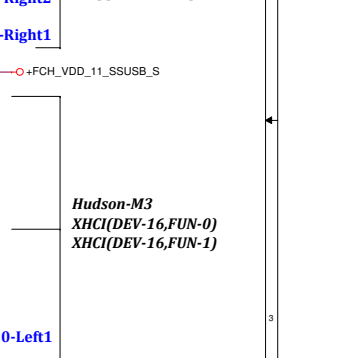
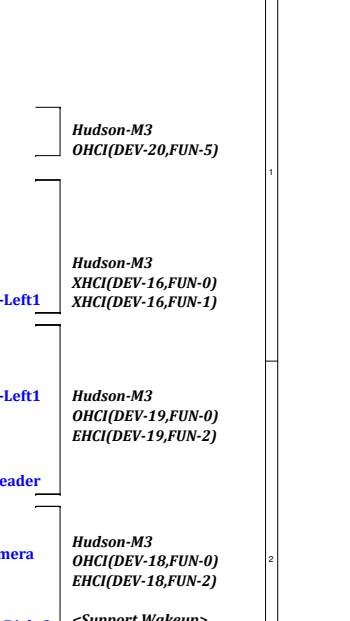
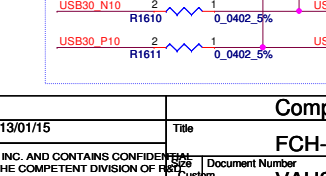
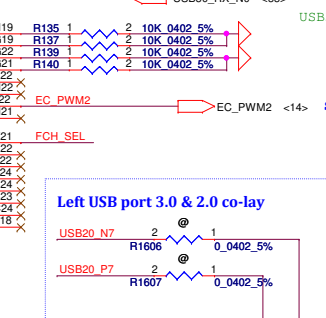
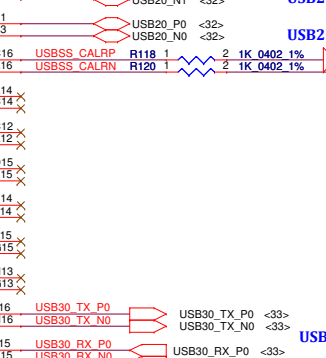
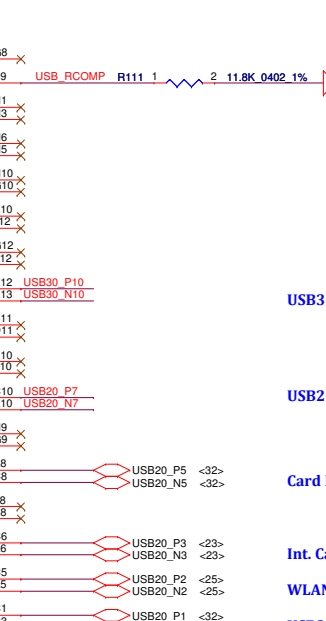
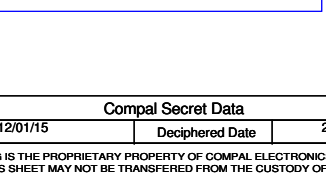
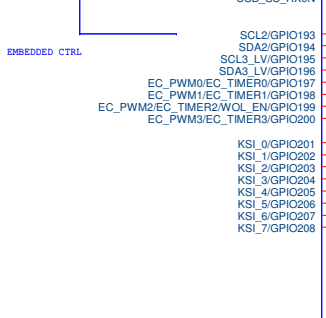
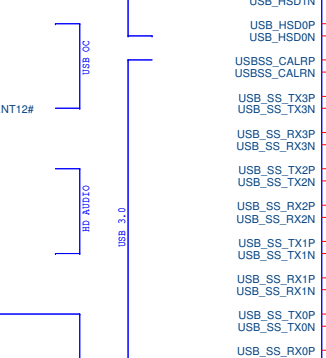
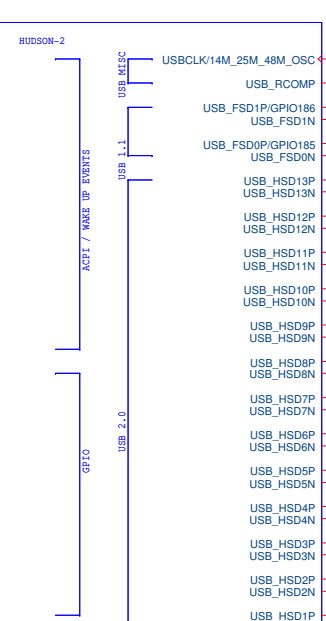
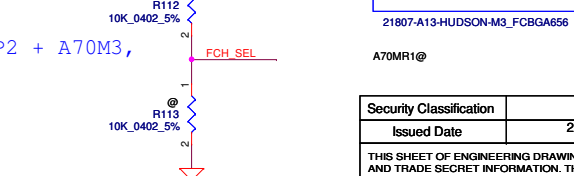
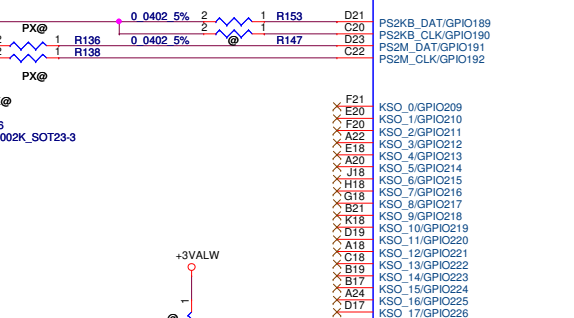
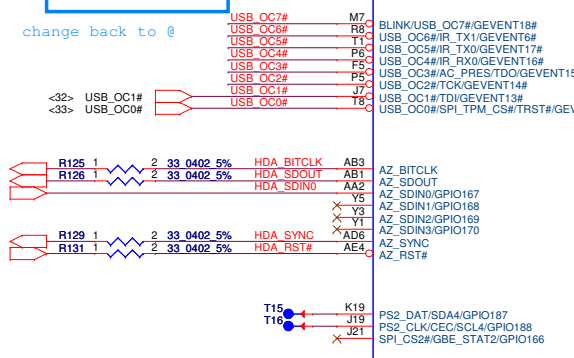
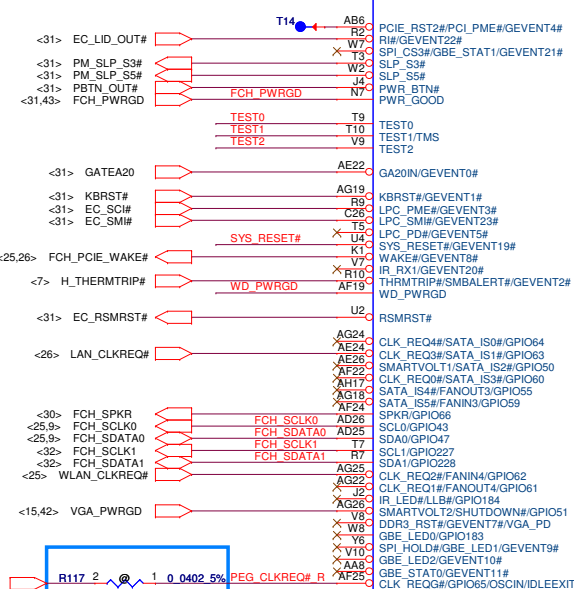


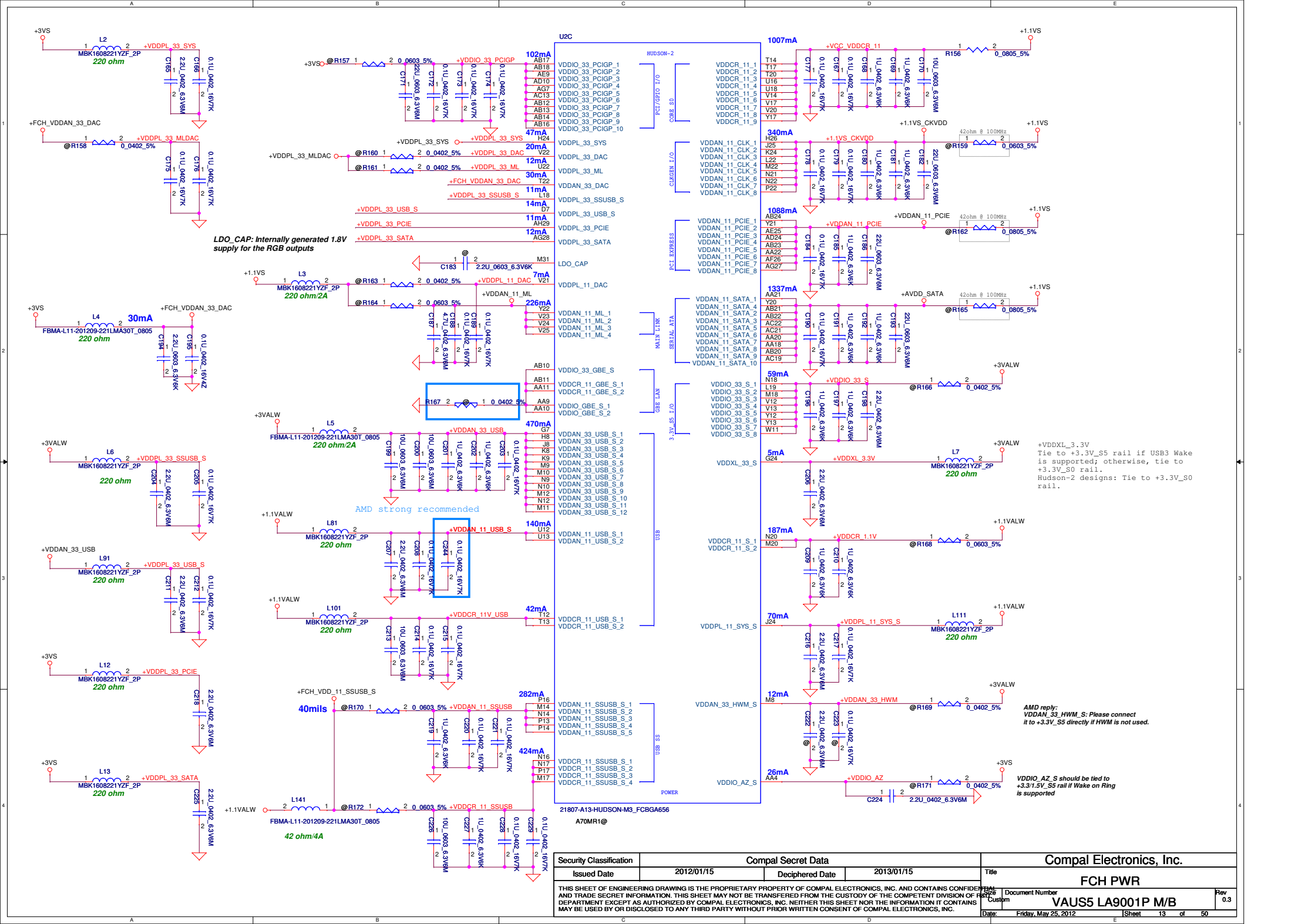
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Date: Friday, May 25, 2012		Sheet 11 of 50			



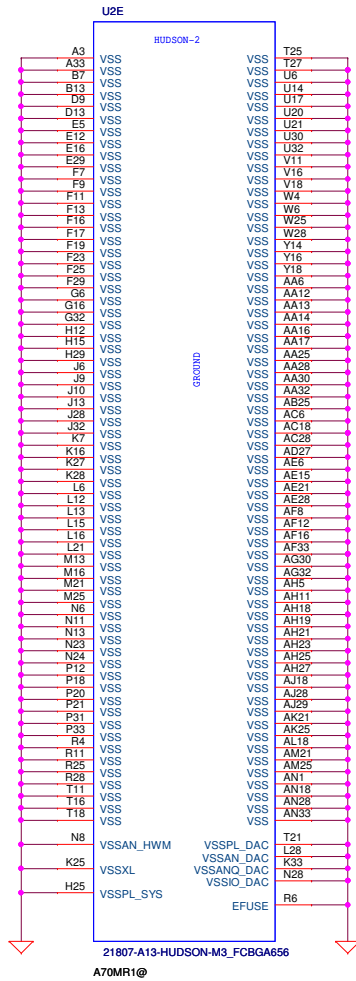
AMD only support FP2 + A70M3,  
@ FCH\_SEL function

### PCIE\_RST2 : Reset PCIE device on Hudson2/3



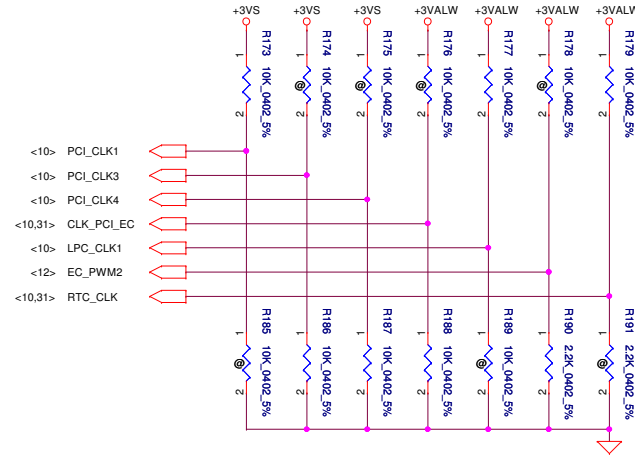


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## STRAP PINS

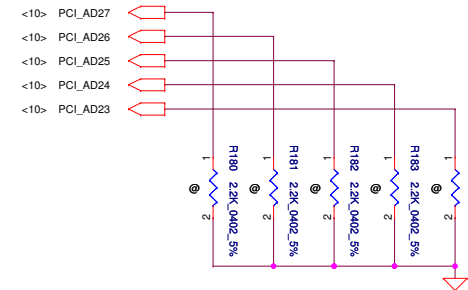
	PCI_CLK1	PCI_CLK3	PCI_CLK4	CLK_PCI_EC	LPC_CLK1	EC_PWM2	RTC_CLK
PULL HIGH	ALLOW PCIE GEN2 DEFAULT	USE DEBUG STRAPS	NON_FUSION CLOCK MODE	EC ENABLED	CLKGEN ENABLED DEFAULT	LPC ROM	S5 PLUS MODE DISABLED DEFAULT
PULL LOW	FORCE PCIE GEN1	IGNORE DEBUG STRAP DEFAULT	FUSION CLOCK MODE DEFAULT	EC DISABLED DEFAULT	CLKGEN DISABLE	SPI ROM DEFAULT	S5 PLUS MODE ENABLED



## DEBUG STRAPS

FCH HAS 15K INTERNAL PU FOR PCI\_AD[27:23]

	PCI_AD27	PCI_AD26	PCI_AD25	PCI_AD24	PCI_AD23
PULL HIGH	USE PCI PLL DEFAULT	DISABLE ILA AUTORUN DEFAULT	USE FC PLL DEFAULT	USE DEFAULT PCIE STRAPS DEFAULT	DISABLE PCI MEM BOOT DEFAULT
PULL LOW	BYPASS PCI PLL	ENABLE ILA AUTORUN	BYPASS FC PLL	USE EEPROM PCIE STRAPS	ENABLE PCI MEM BOOT

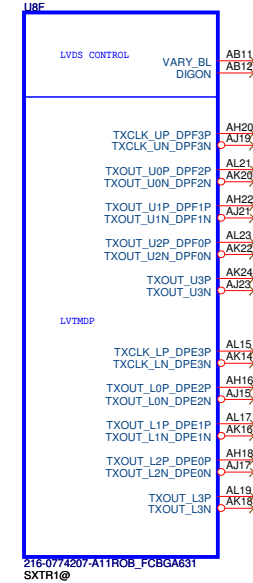
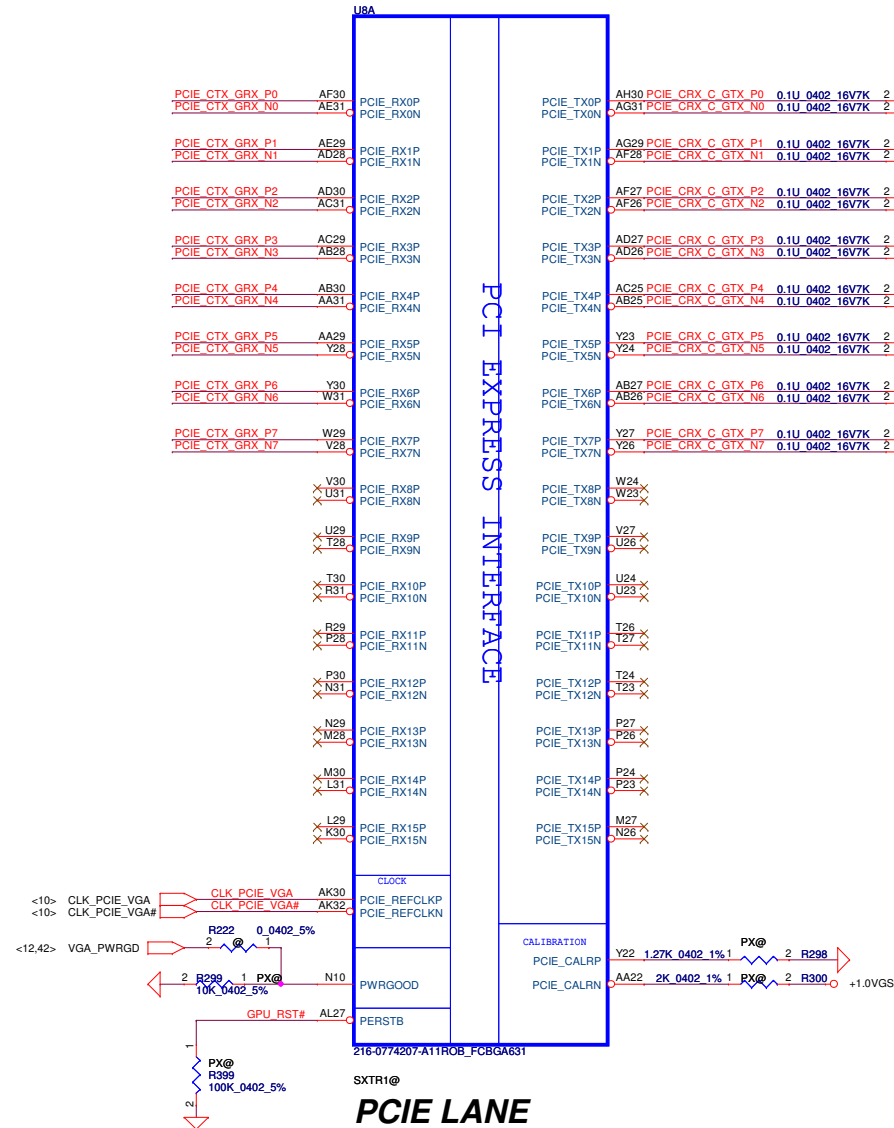


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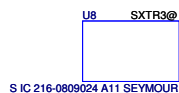
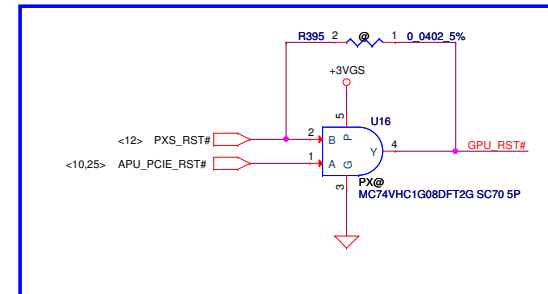


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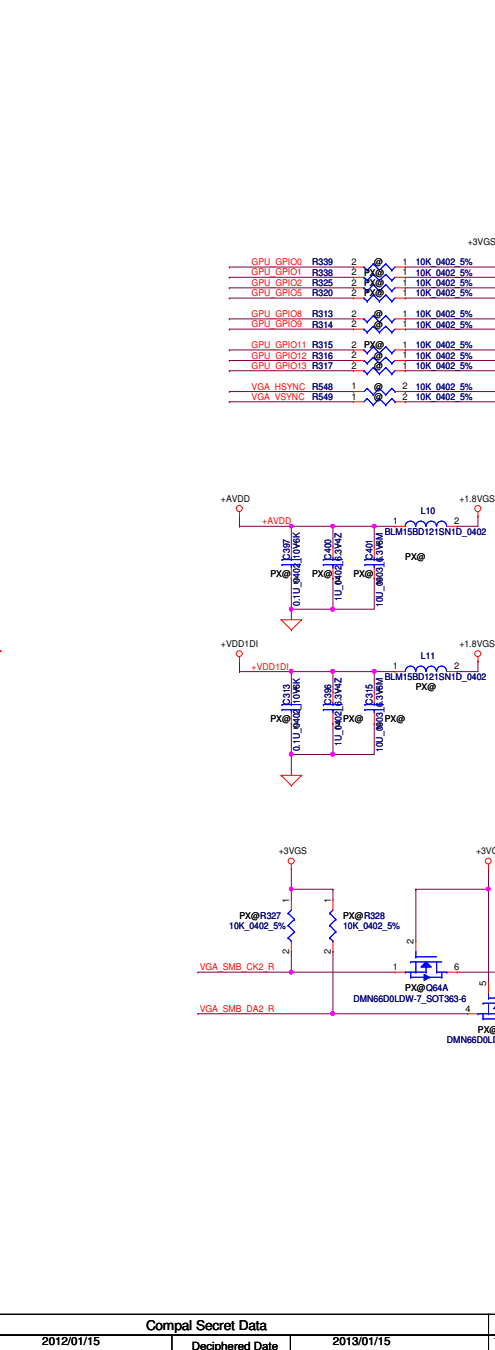
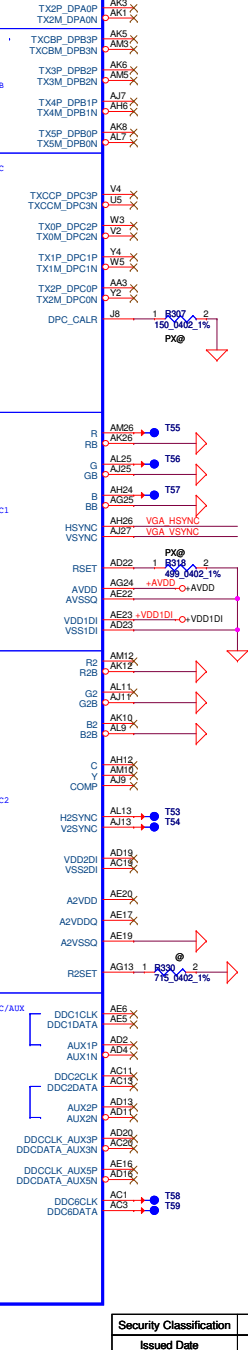
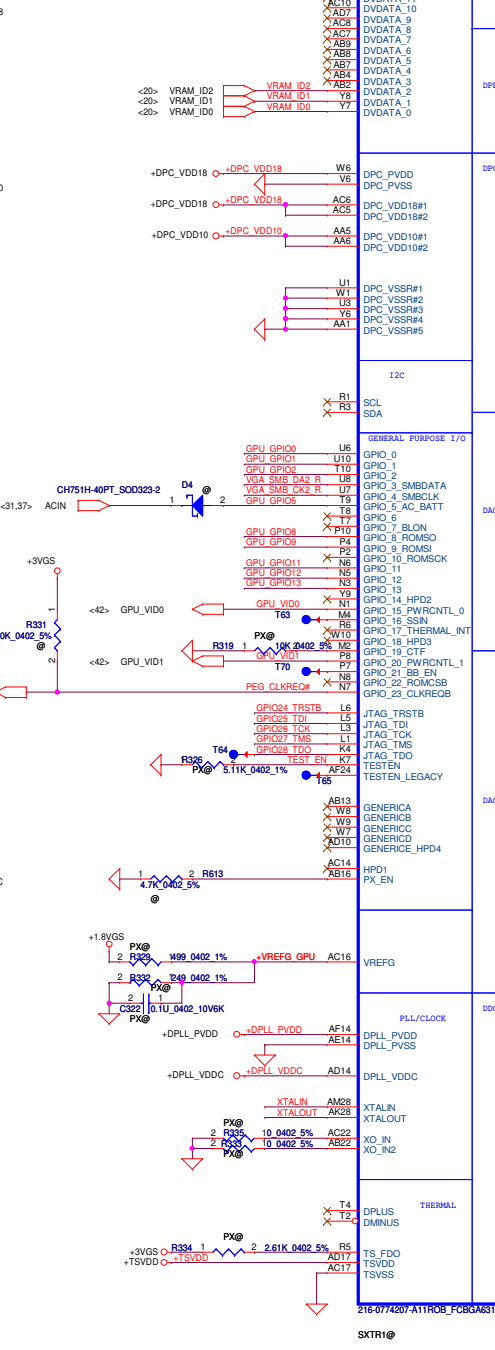
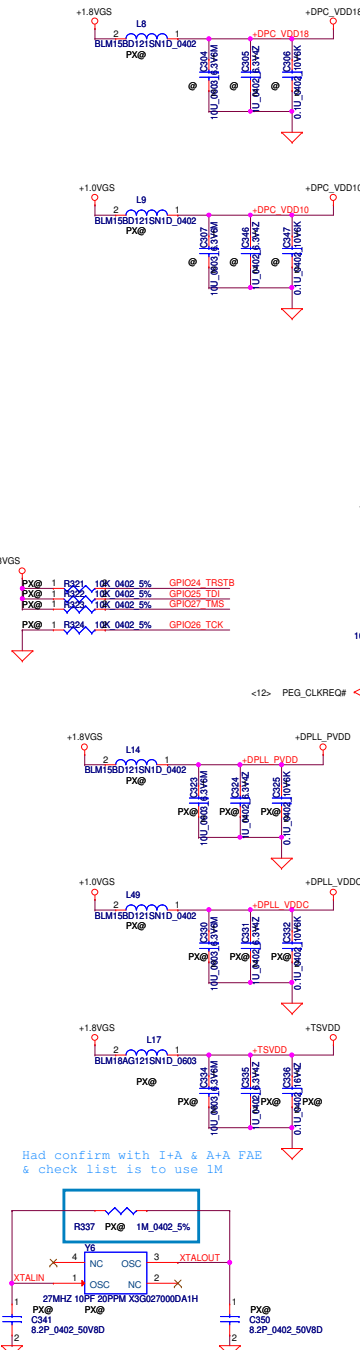
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PCIE\_CRX\_GTX\_N[7..0] PCIE\_CRX\_GTX\_N[7..0] <5>



LVDS



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				VAUS5 LA9001P M/B	0.3
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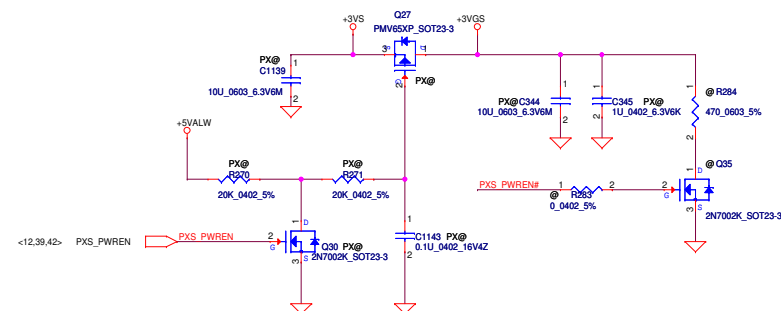
Had confirm with I+A & A+FAE  
& check list is to use 1M

change Y6 follow QAWYA (SJ10000FH00)

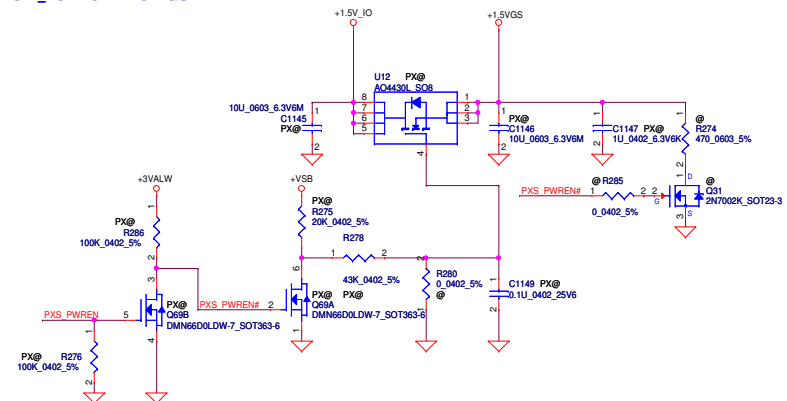
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Issued Date		Deciphered Date		Title	
2012/01/15		2013/01/15		Seymour-XT-S3 Main Gen/MSIC	
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**+3.3VS TO +3.3VGS**



+1.5V\_IO TO +1.5VGS

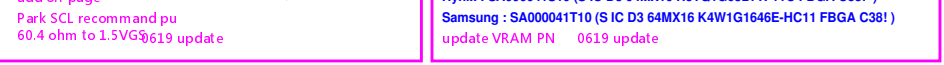
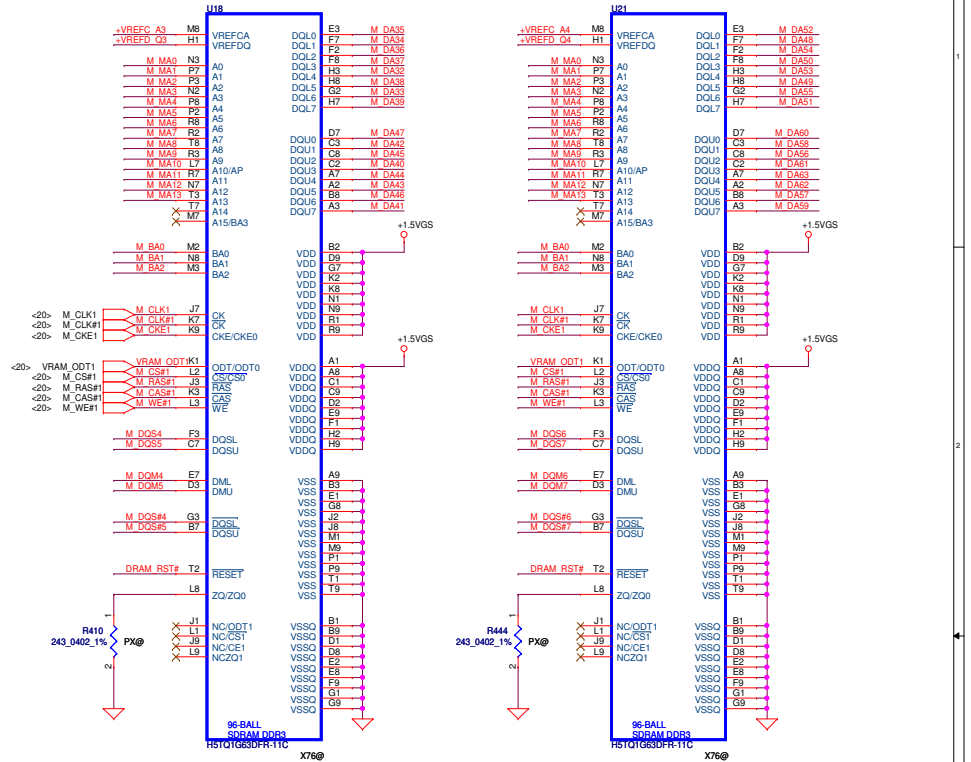


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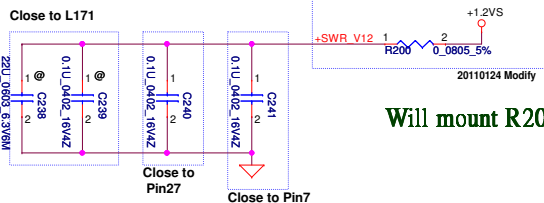
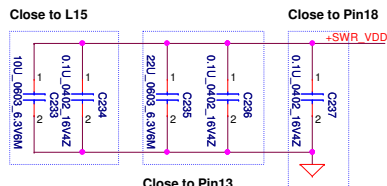
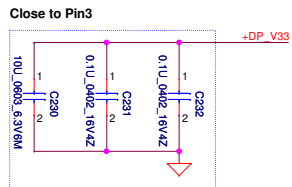
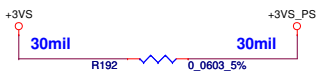






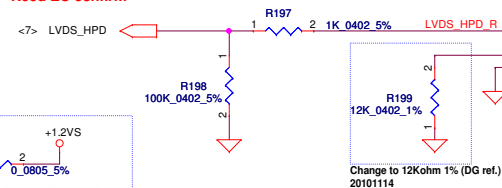


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Date:		Expiry:		Rev:	
2012/01/15		2013/01/15		0.3	

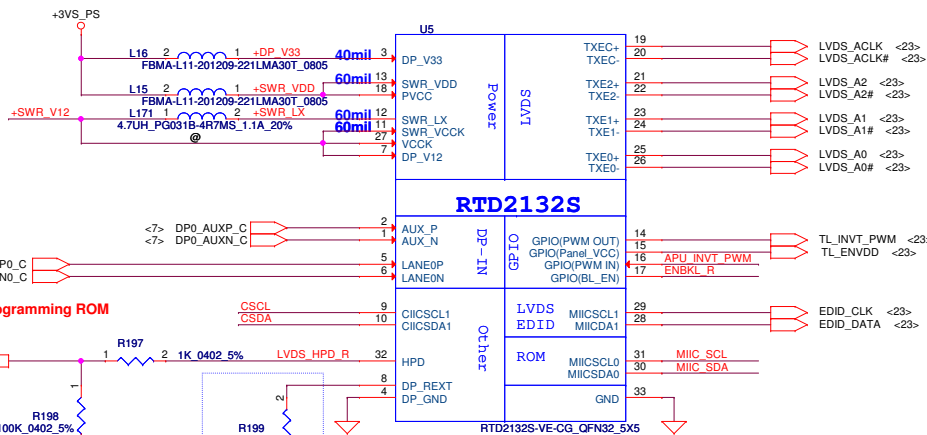
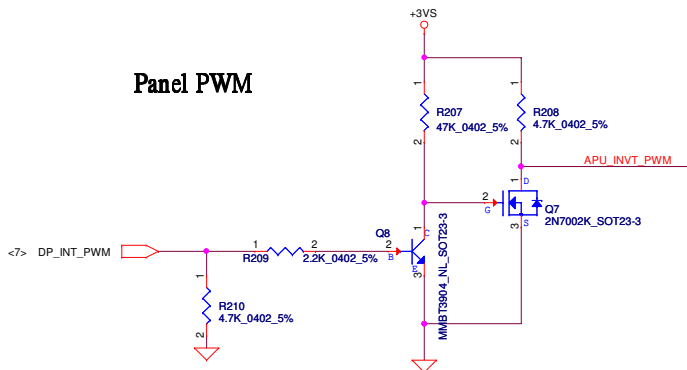


Will mount R200, @ L171, C238, C239 after DVT

Reserved for EC programming ROM  
Need EC confirm

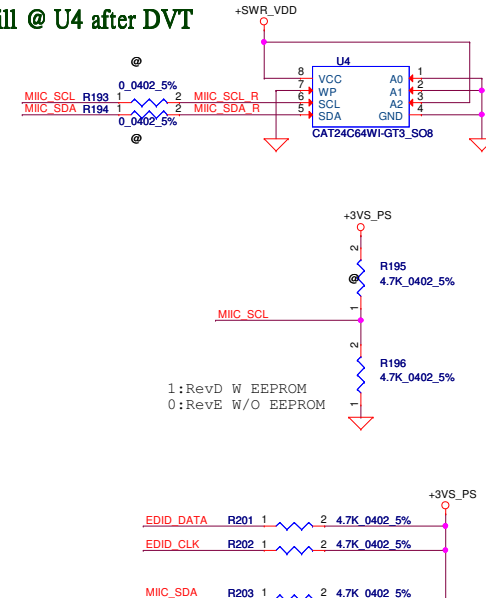


## Panel PWM

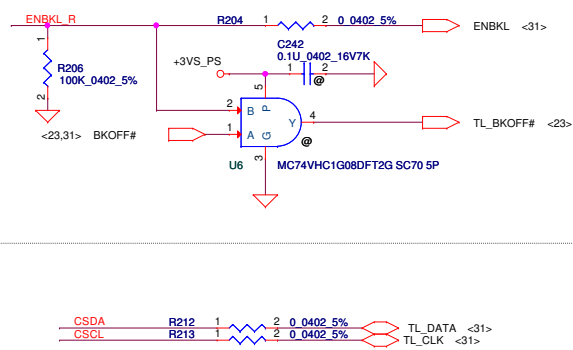


## EEPROM

Will @ U4 after DVT

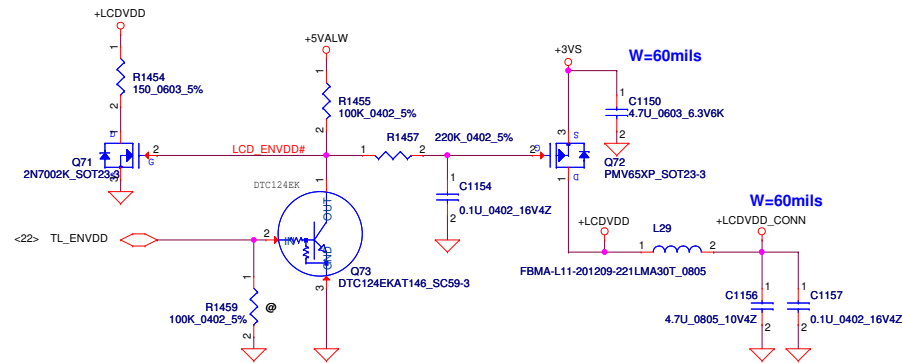


Vendor advise reserve it  
(We delete the 0ohm path between ENBKL\_R & TL\_BKOFF#)

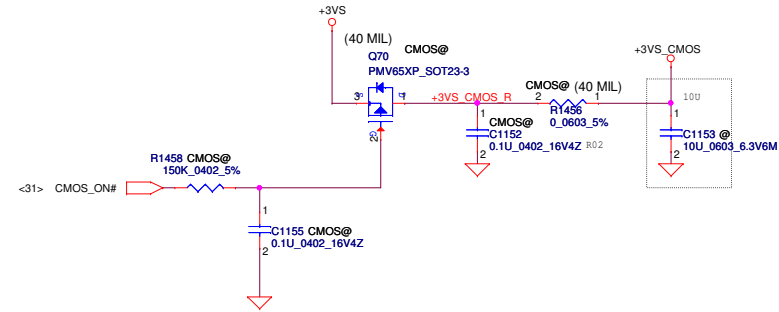
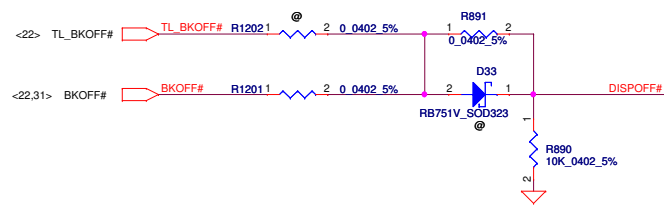


Security Classification		Compal Secret Data		Compal Electronics, Inc.	
Issued Date	2012/01/15	Deciphered Date	2013/01/15	Title	LVDS Translator - RTD2132S
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				Date	Friday, May 25, 2012
				Sheet	22 of 50

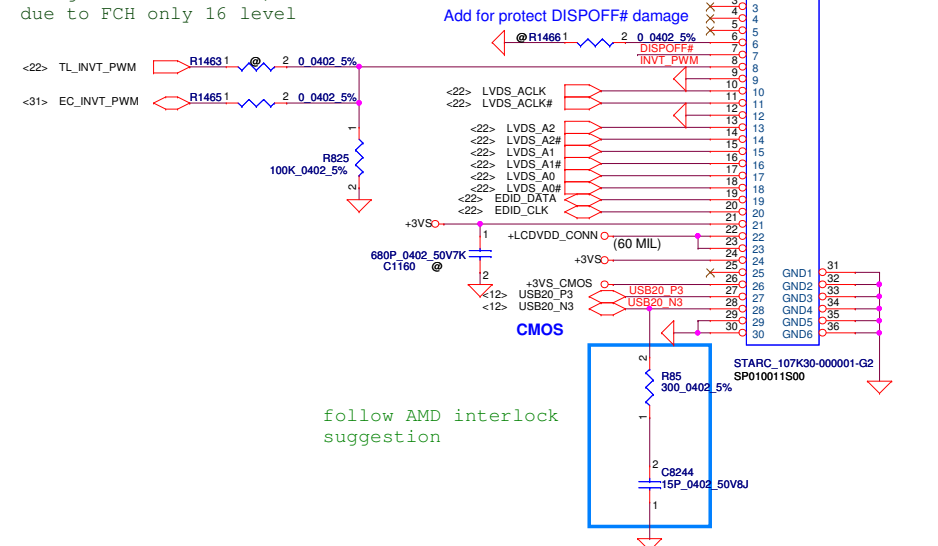
## LCD POWER CIRCUIT



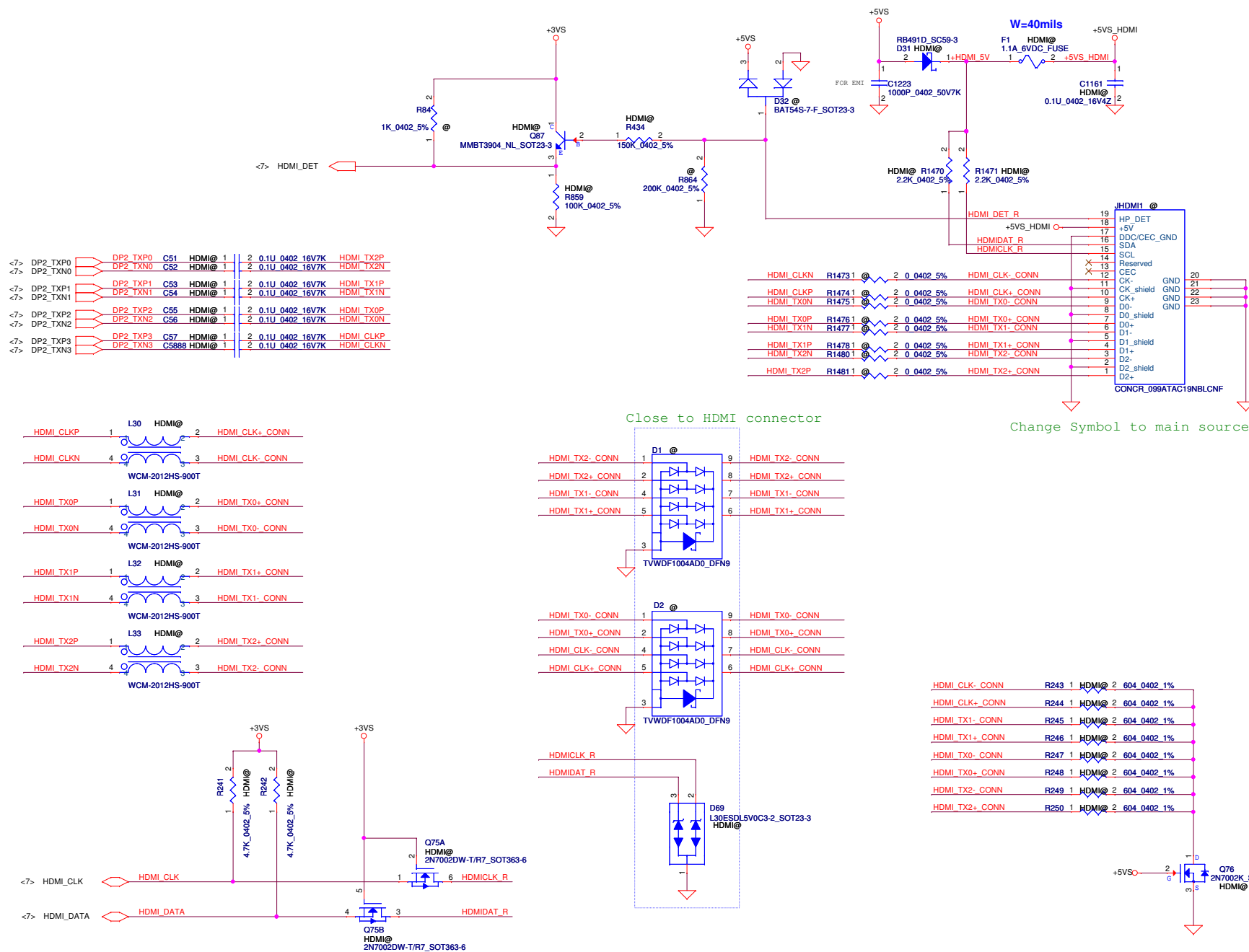
## CMOS Camera

**VGA LCD/PANEL BD. Conn.**

change to EC control ,  
due to FCH only 16 level



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Issued Date	2012/01/15	Deciphered Date	2013/01/15	Title	
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				CUSTOMER <b>VAU55 LA9001P M/B</b>	0.3
Date:				Thursday, May 31, 2012	Sheet 23 of 50

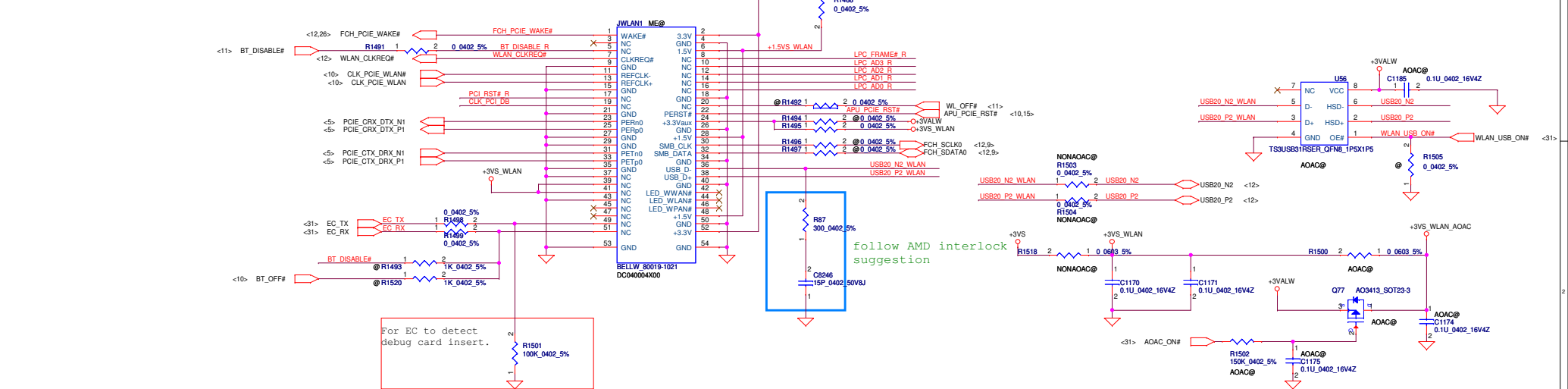


Security Classification		Compal Secret Data		Title	
Issued Date	2012/01/15	Deciphered Date	2013/01/15	Compal Electronics, Ltd.	
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				VAUSS LA9001P M/B	0.3
Date: Friday, May 25, 2012				Sheet	24 of 50



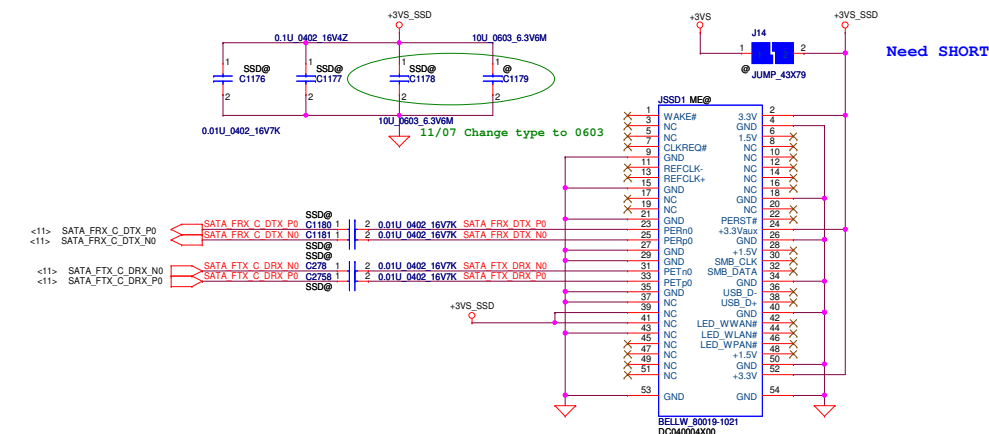
Mini-Express Card for WLAN/WiMAX(Half)

Mini-Express Card(WLAN/WiMAX)

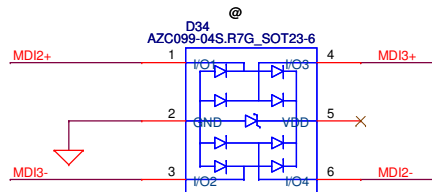


Mini-Express Card for SSD(Full)

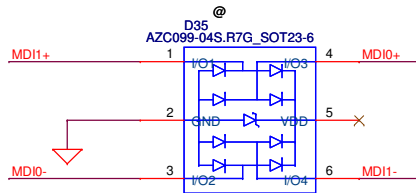
Mini-Express Card(WWAN/SSD) SSD Active:4.5W(1.5A)





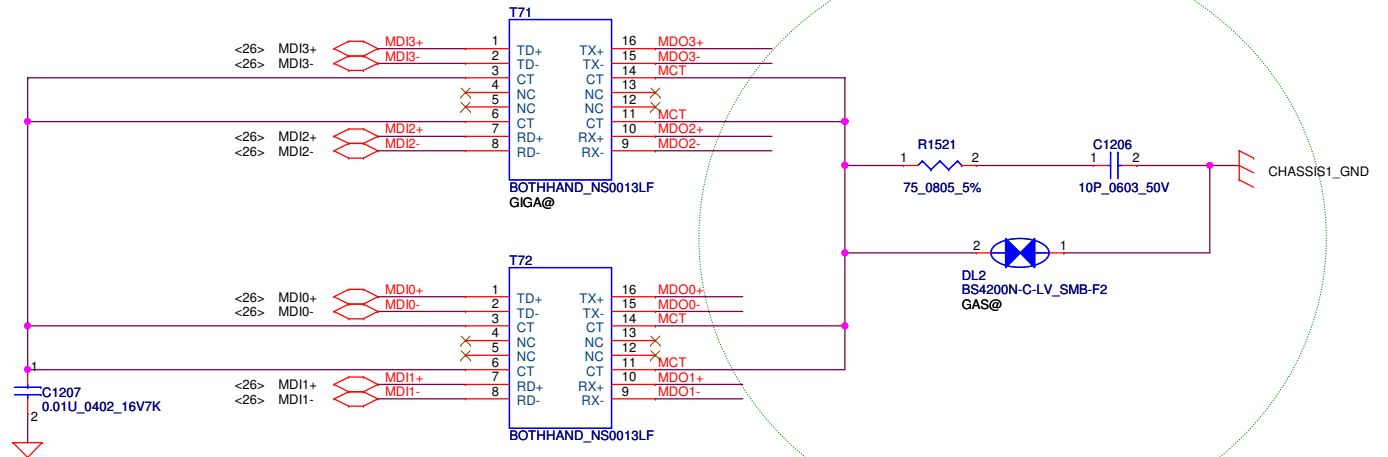


Place Close to T71

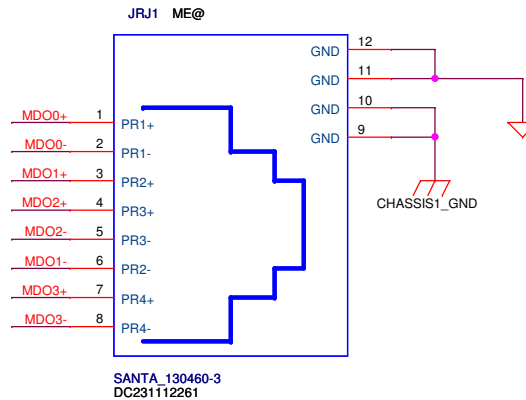


Place Close to T72

D34/D35  
1'S PN:SC300001G00  
2'S PN:SC300002E00

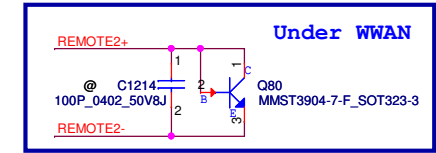
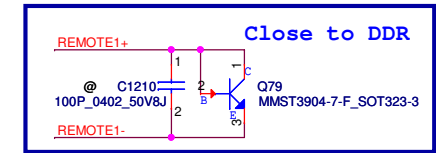
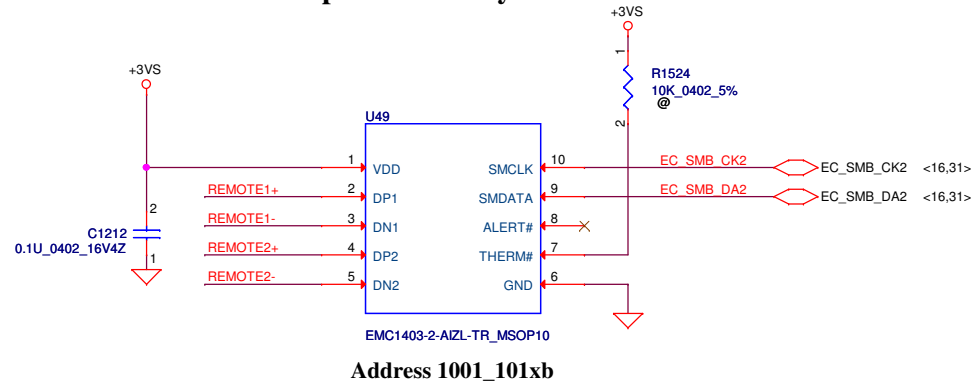
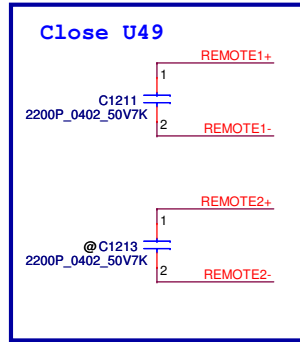


Place Close to T71,T72



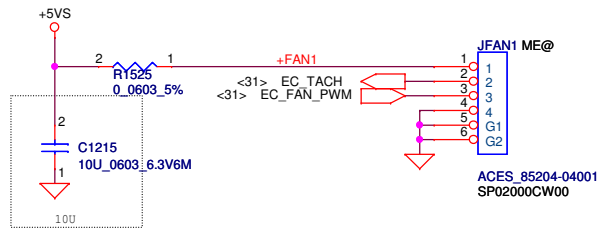
Security Classification		Compal Secret Data		Compal Electronics, Inc.	
Issued Date	2012/01/15	Deciphered Date	2013/01/15	Title	LAN_Transformer
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				Document Number	0.3
				Date:	Friday, May 25, 2012
				Sheet	27 of 50

# SMSC thermal sensor placed near by VRAM

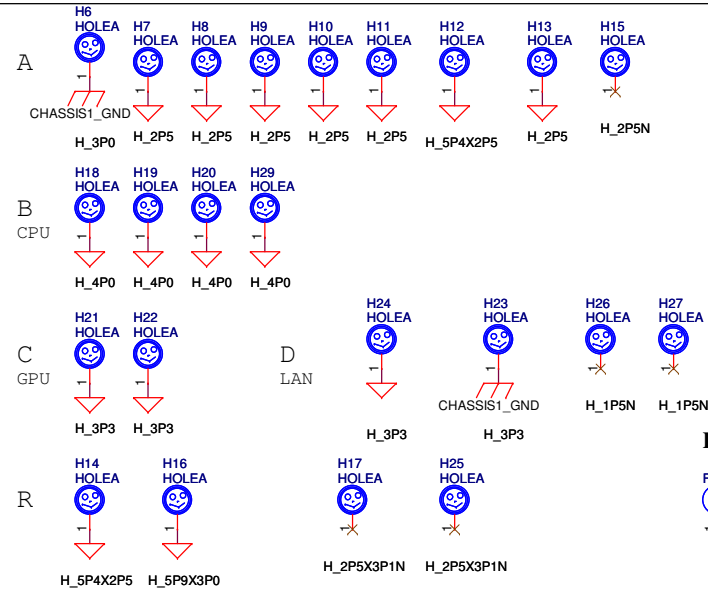


REMOTE1,2+/-:  
Trace width/space:10/10 mil  
Trace length:<8"

## FAN1 Conn



## Screw Hole



## PCB Federal Mark PAD

Security Classification	Compal Secret Data			Compal Electronics,Ltd.	
Issued Date	2012/01/15	Deciphered Date	2013/01/15	Title	Fintek-Thermal IC/FAN/screw
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				Rev	0.3
				Date: Friday, May 25, 2012	Sheet 28 of 50

[illegible]

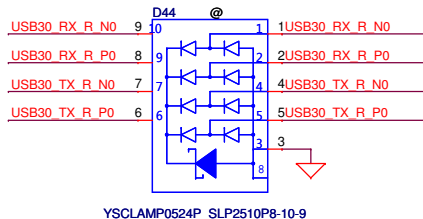
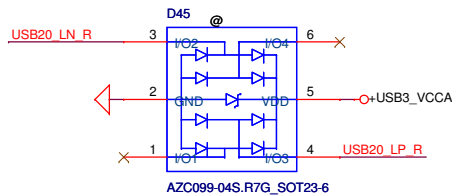
Security Classification		Compal Secret Data		<b>Compal Electronics, Inc.</b> <b>HDD Connector</b>	
Issued Date	2012/01/15	Deciphered Date	2013/01/15	Title	
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				Customer	<b>VAU55 LA9001P M/B</b> Date: Friday, May 25, 2012
				Sheet	29 of 50



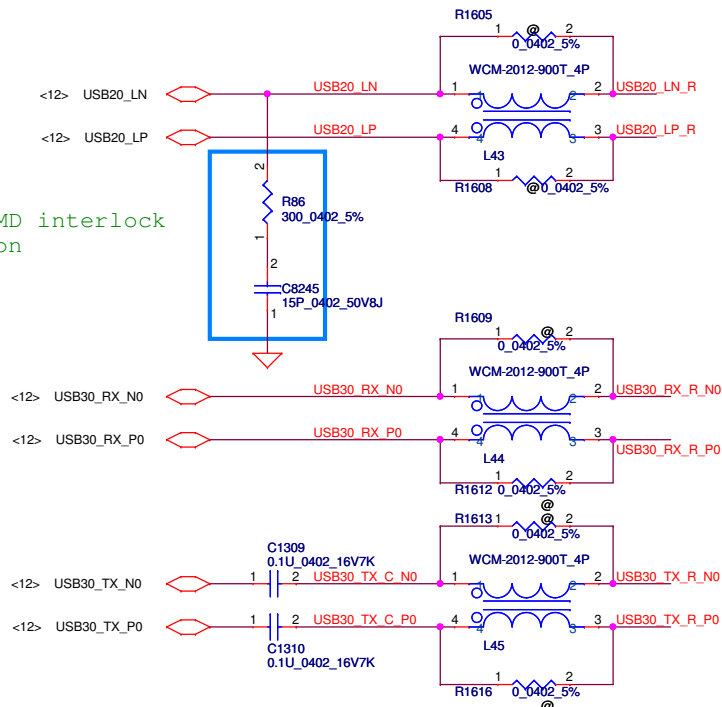




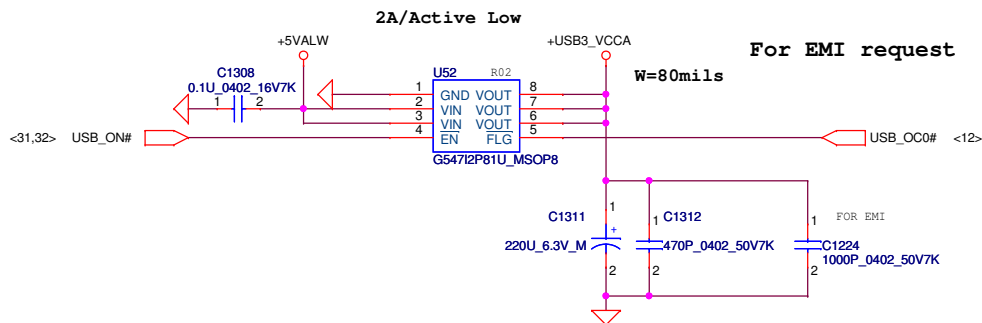
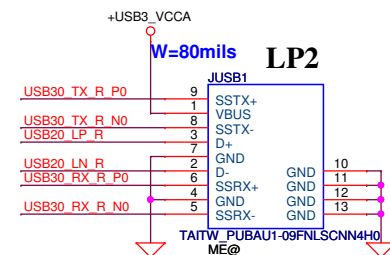




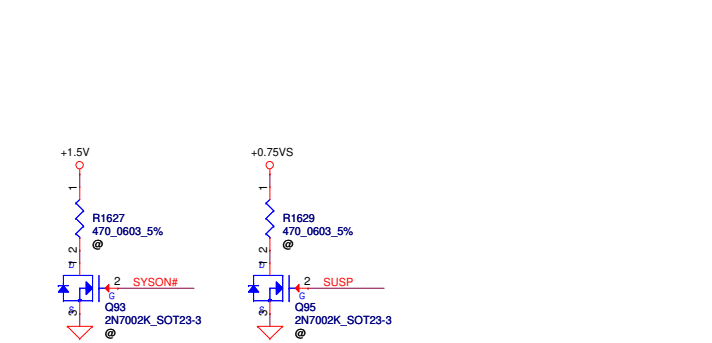
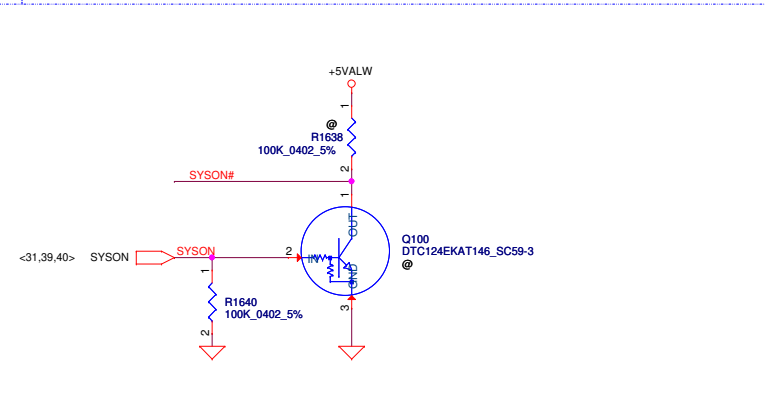
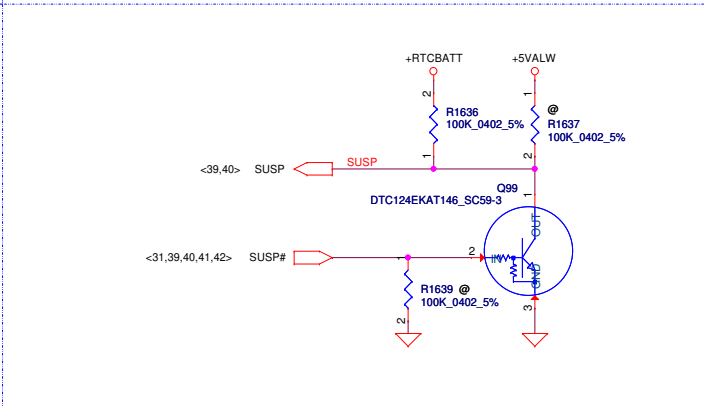
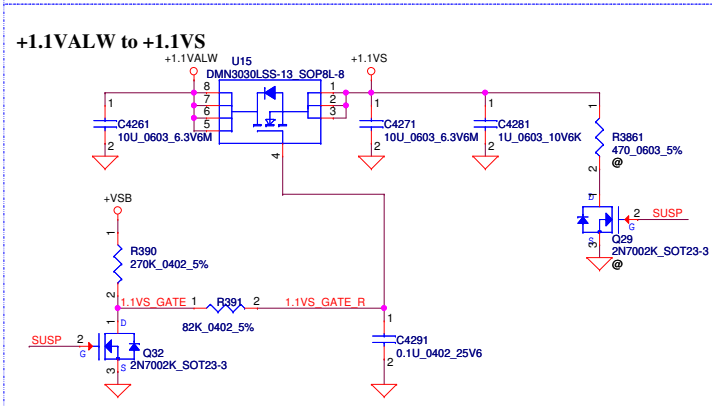
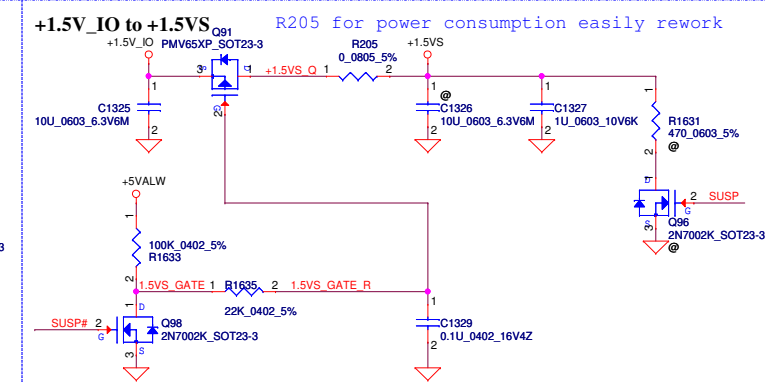
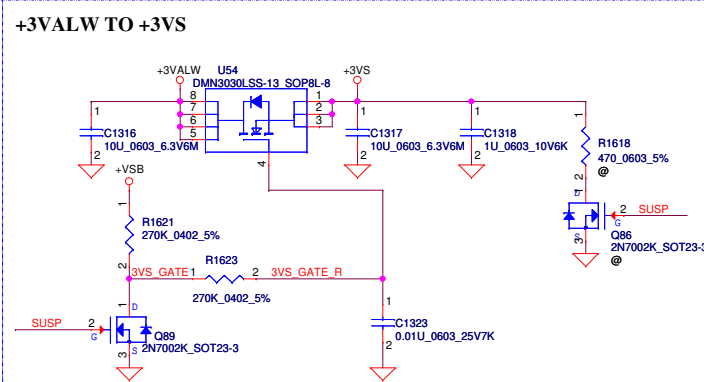
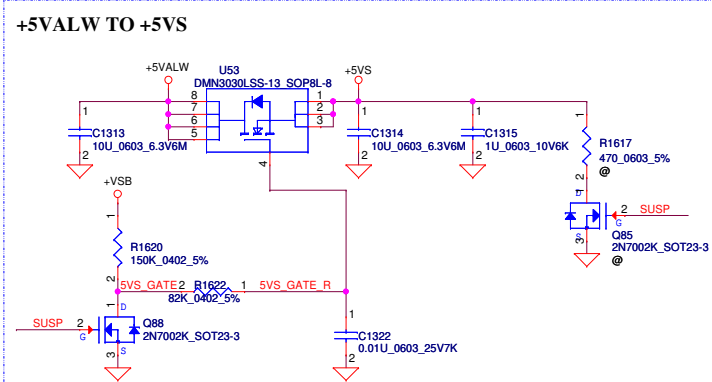
follow AMD interlock suggestion



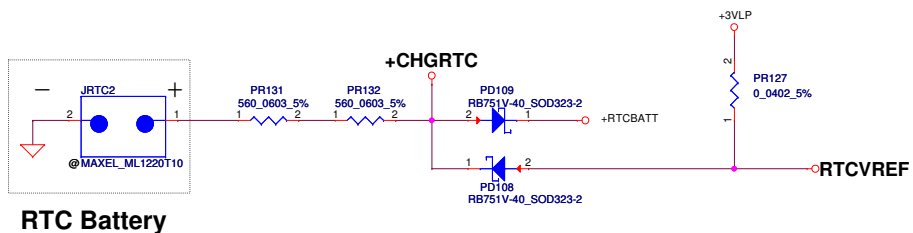
Place TX AC coupling Cap (C1309,C1310) . Close to connector



Security Classification		Compal Secret Data For EMI request		Title	
Issued Date	2012/01/15	Deciphered Date	2013/01/15	USB3.0 ports	
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				VAUS5 LA9001P M/B	0.3
Date: Thursday, May 31, 2012				Sheet 33 of 50	

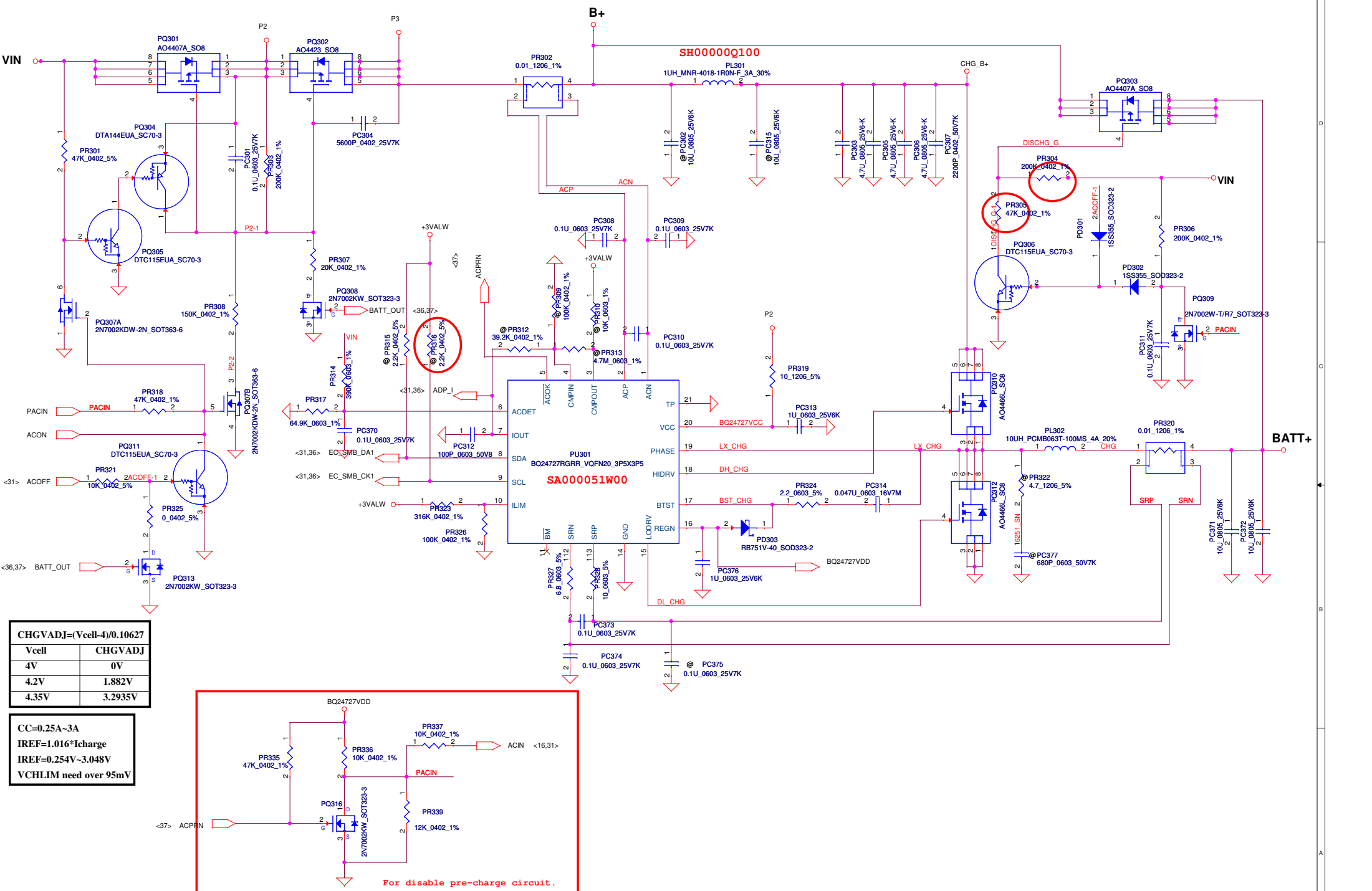


Security Classification		Compal Secret Data				Compal Electronics, Inc.					
Issued Date		2011/06/30		Deciphered Date		2013/06/30		Title			
								DC-DC INTERFACE			
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						Custom	VAU55 LA9001P M/B		0.3		
						Date:	Friday, May 25, 2012	Sheet	34	of	50



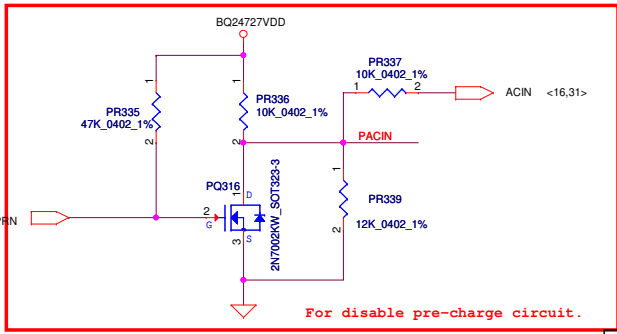
Security Classification	Compal Secret Data			Compal Electronics, Inc.		
Issued Date	2011/10/12	Deciphered Date	2013/10/12	Title	PWR DCIN / Vin Detector /Pre-charge	
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				Rev	0.1	
				Date:	Friday, May 25, 2012	Sheet 35 of 48





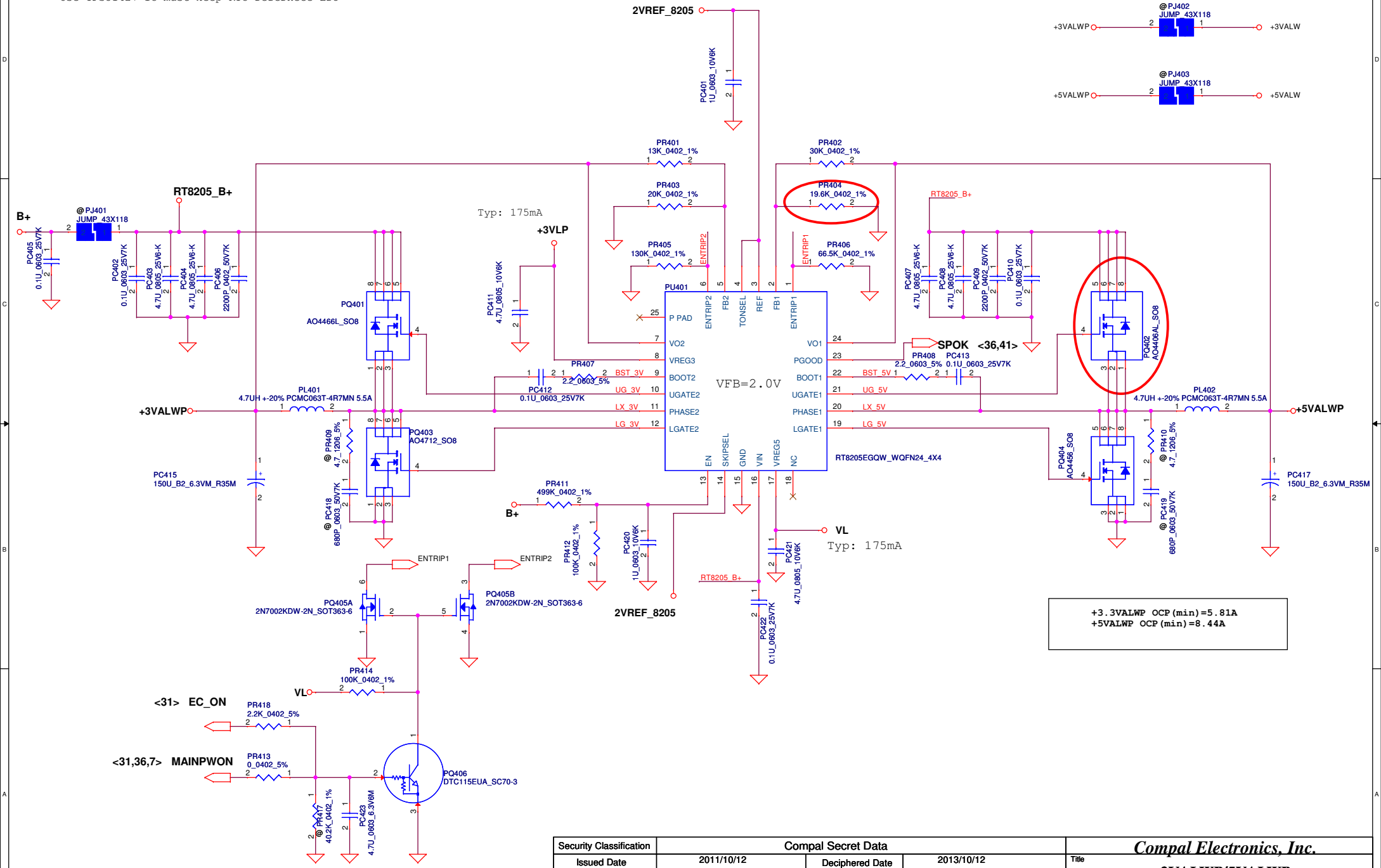
CHGVADJ=(Vcell-4)/0.10627	
Vcell	CHGVADJ
4V	0V
4.2V	1.882V
4.35V	3.2935V

CC=0.25A~3A	
IREF=1.016*Icharge	
IREF=0.254V~3.048V	
VCHLIM need over 95mV	



Security Classification		Compal Secret Data		Compal Electronics, Inc.	
Issued Date	2011/10/12	Deciphered Date	2013/10/12	Title	CHARGER
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				Date	Friday, May 25, 2012
				Sheet	37 of 48
				Rev	0.1
				LA9001P	

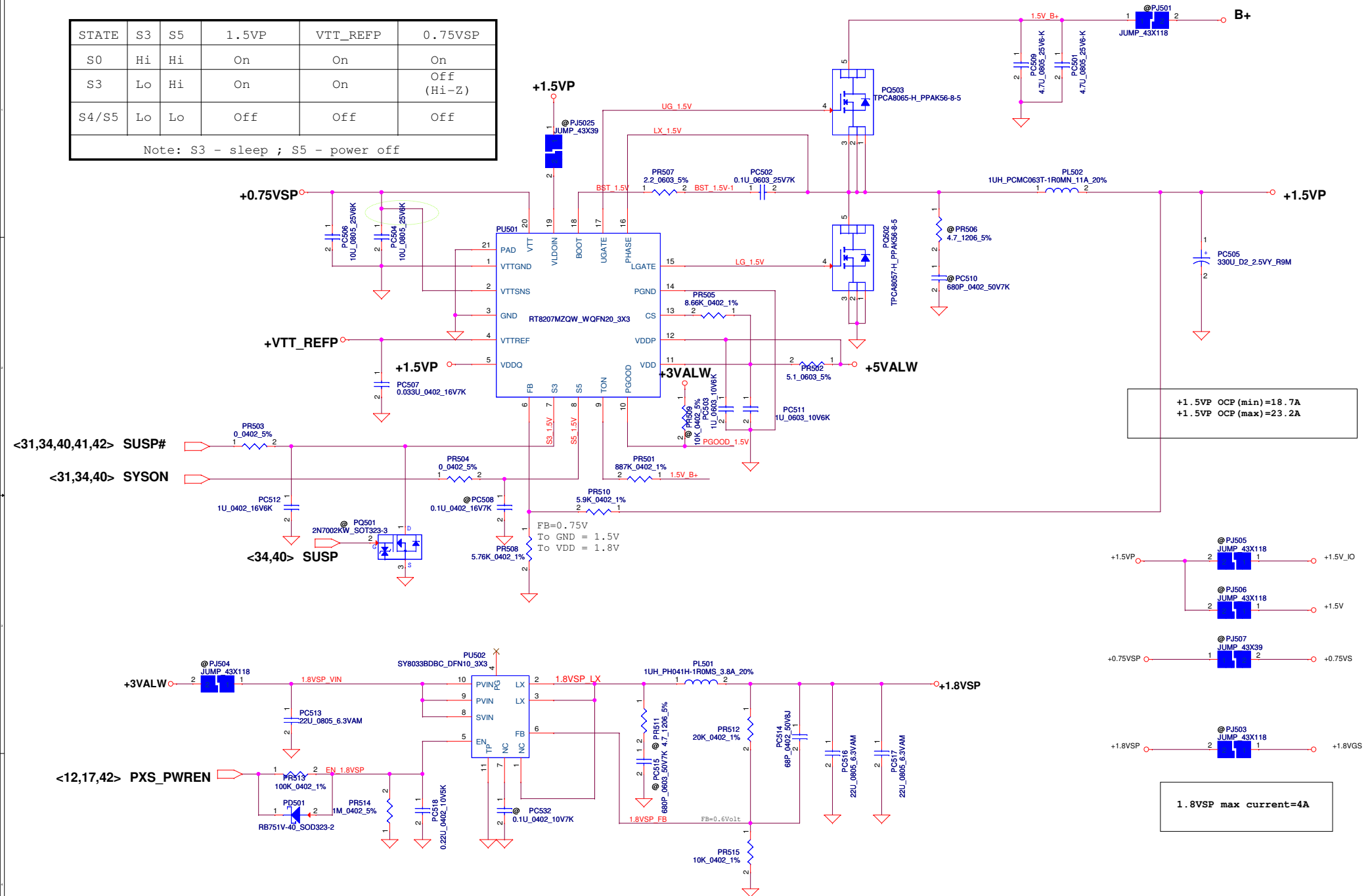
Note:  
 Use TPS51125 IC can remove RTC refernece LDO  
 Use TPS51427 IC must keep RTC refernece LDO



Security Classification		Compal Secret Data		Title	
Issued Date	2011/10/12	Deciphered Date	2013/10/12	3VALWP/5VALWP	
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				Document Number	LA9001P
				Date: Friday, May 25, 2012	Sheet 38 of 48

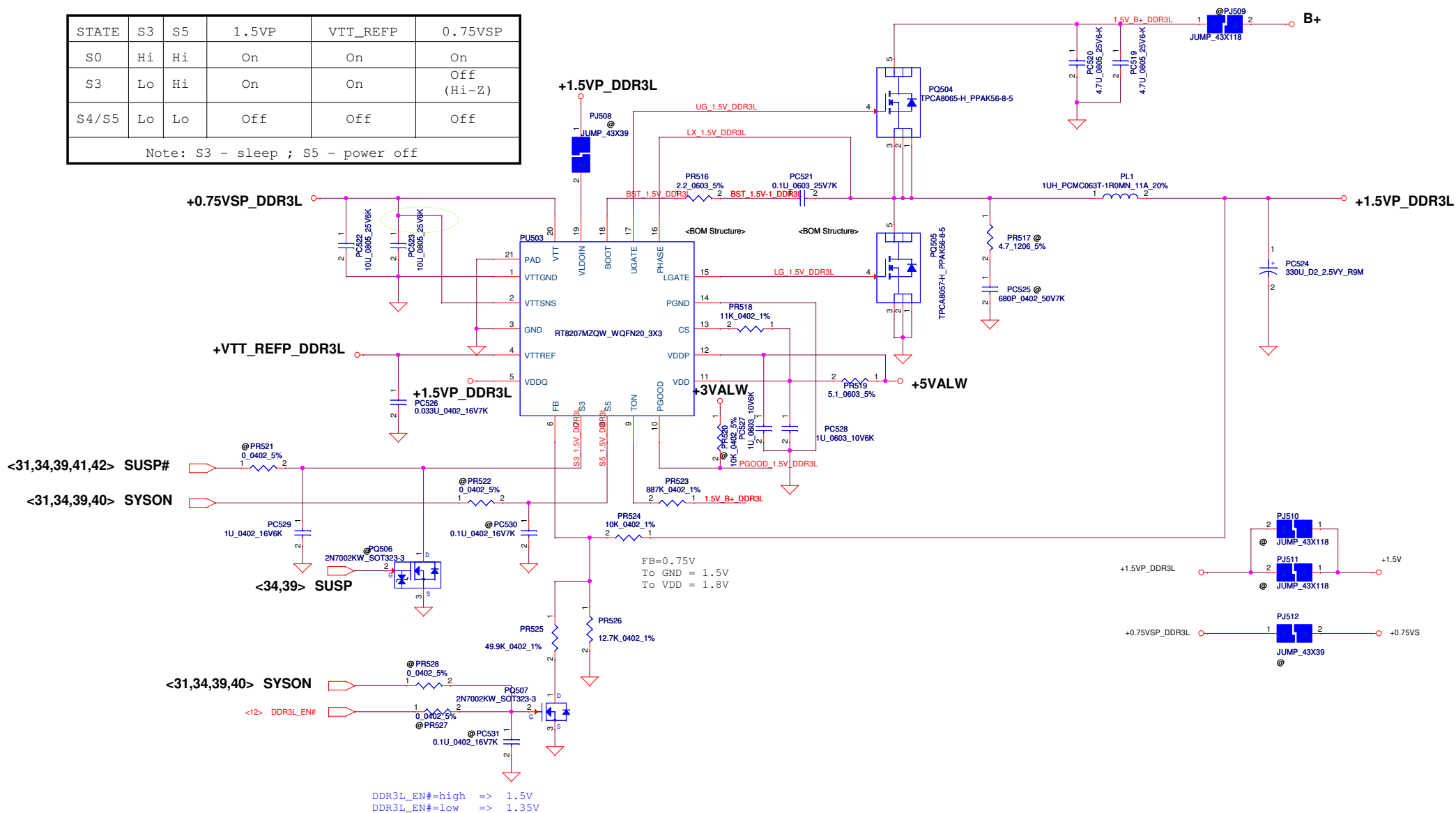
STATE	S3	S5	1.5VP	VTT_REFP	0.75VSP
S0	Hi	Hi	On	On	On
S3	Lo	Hi	On	On	Off (Hi-Z)
S4/S5	Lo	Lo	Off	Off	Off

Note: S3 - sleep ; S5 - power off

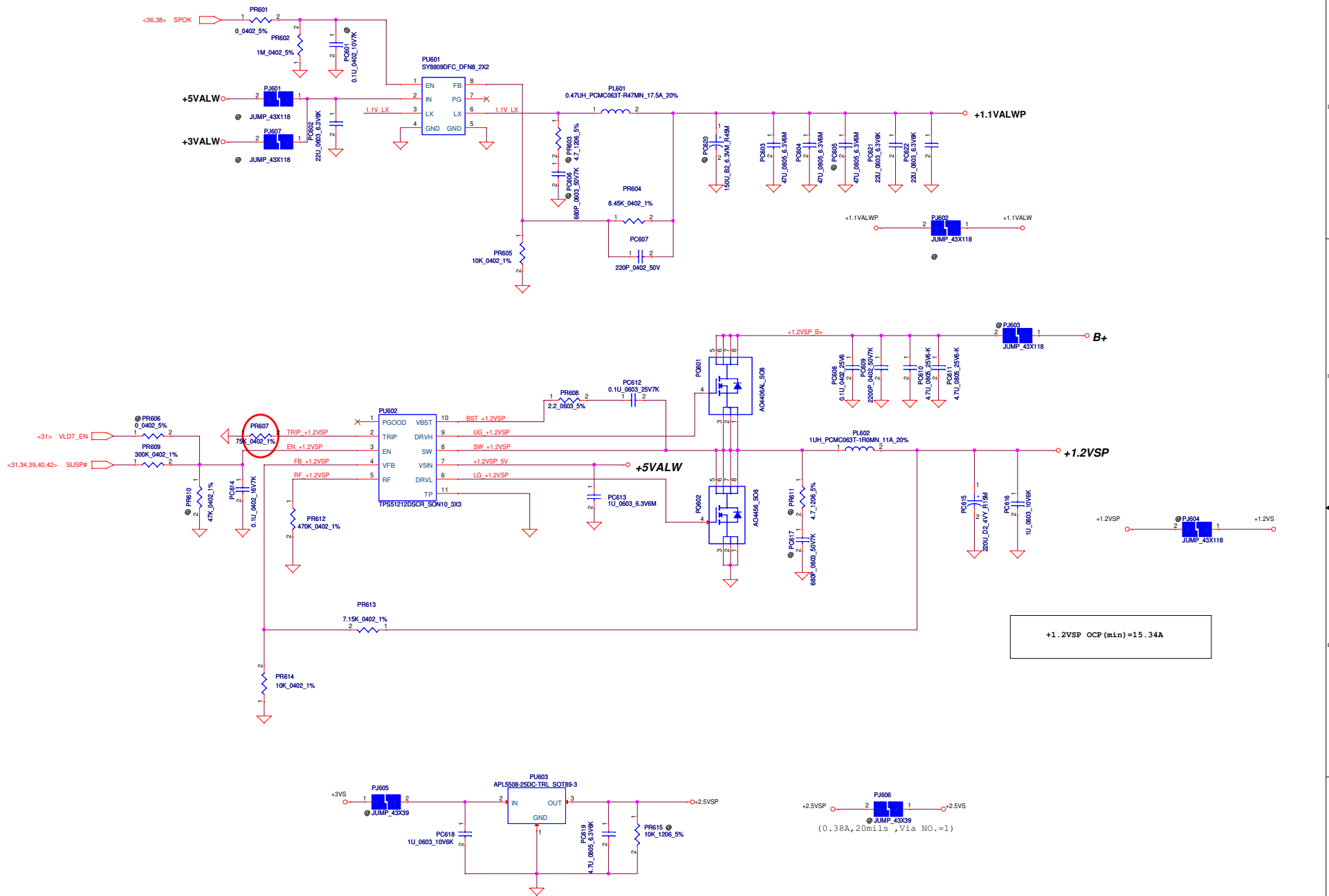


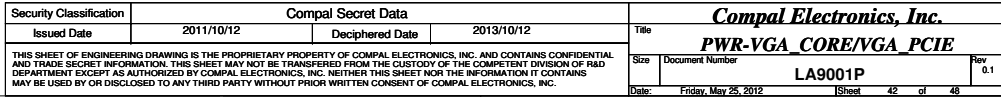
STATE	S3	S5	1.5VP	VTT_REFP	0.75VSP
S0	Hi	Hi	On	On	On
S3	Lo	Hi	On	On	Off (Hi-Z)
S4/S5	Lo	Lo	Off	Off	Off

Note: S3 - sleep ; S5 - power off

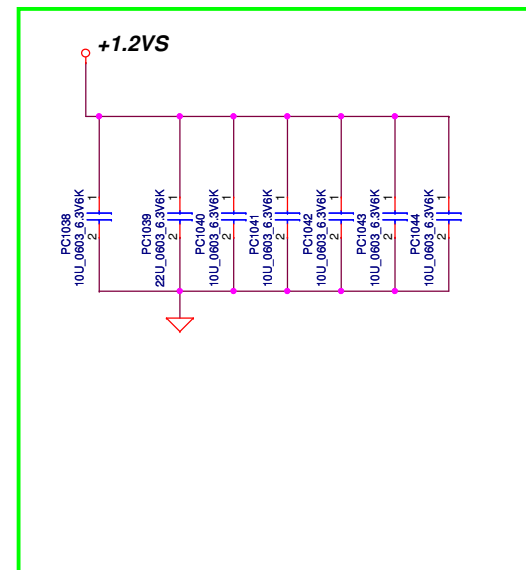
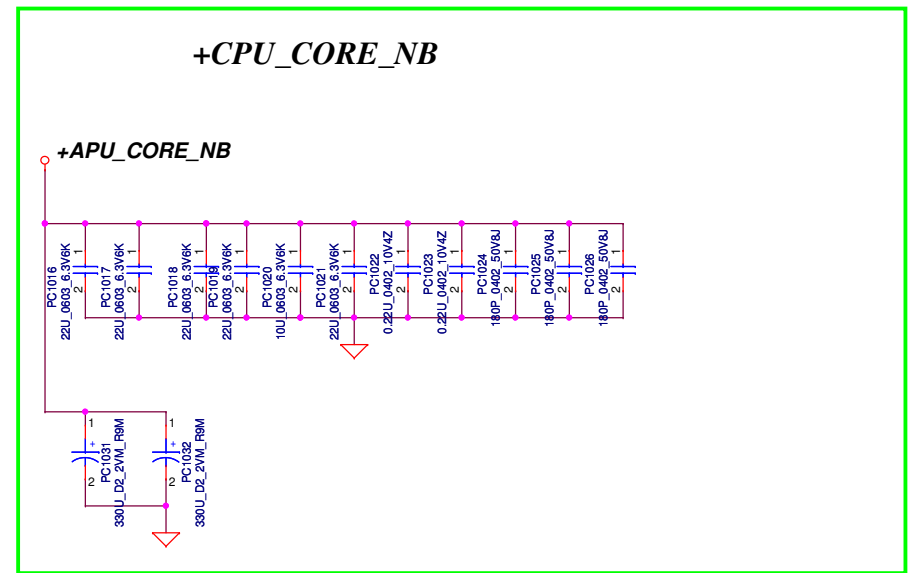
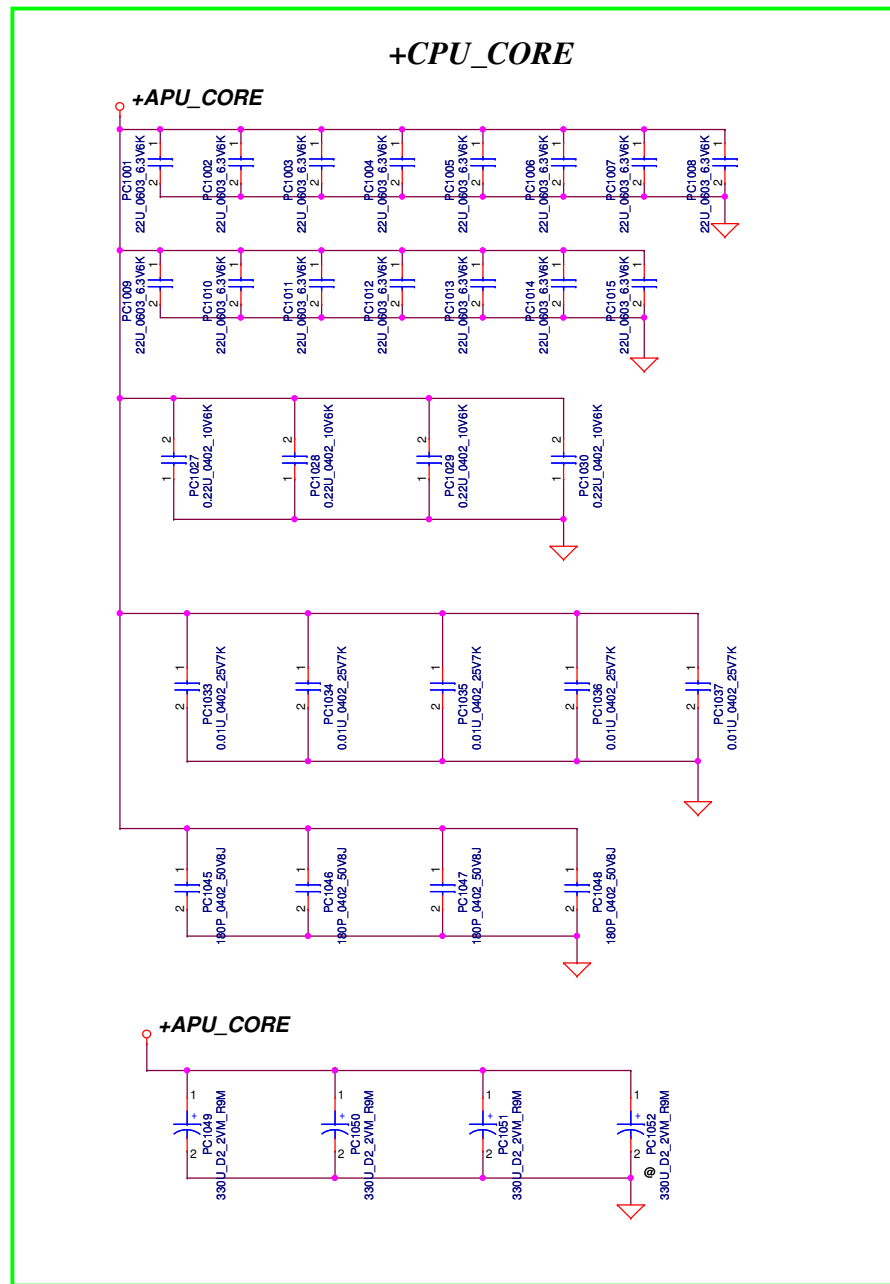












Security Classification		Compal Secret Data		<b>Compal Electronics, Inc.</b>			
Issued Date	2011/10/12	Deciphered Date	2013/10/12	Title	<b>PWR - PROCESSOR DECOUPLING</b>		
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					LA9001P	0.1	
				Date:	Friday, May 25, 2012	Sheet 44 of 48	

Item	Reason for change	PG#	Modify List	Date	Phase
1					
2					
3					
4					
5					
6					
7					
8					
9					
10					
11					
12					
13					
14					
15					
16					
17					

VAUS5 HW PIR List

SDV TO SIV

NO	DATE	PAGE	MODIFICATION LIST	PURPOSE	NOTE
1	3/22	26	Change C1204, C1205 from SE071120JN0 to SE071120J80	SE071120JN0 is for A58 only	
2	3/22	27	Modify DL2 from @ to GAS@	For Gastube BOM control	
3	3/22	12	Delete FCH_SEL BOM control	AMD formal announce FP2 only support A70M3	
4	3/22	10	Delete U2 A60MR1 BOM control	AMD formal announce FP2 only support A70M3	
5	3/22	12	Change R117 from PX@ to @, change R155 from @ to always mount	Clock request from GPU will not meet power sequence	
6	3/22	12	Change R1606, R1607 from USBL2@ to @, change R1610, R1611 from USBL3@ to always mount	AMD formal announce FP2 only support A70M3	
7	3/26	10	Change GPIO31 pull high from +3VALW to +3VS	This GPIO pin is Core power rail	
8	4/2	07	Add R215 to pull high +1.5V_APU & @ R36	AMD suggest	
9	4/6	24	Add C1223 1000p	For EMI	
10	4/6	33	Add C1224 1000p	For EMI	
11	4/6	26	Change C1204, C1205 from 12p to 15p	For Vendor tuning value	
12	4/6	16	Change C341, C350 from 15p to 8.2p	For Vendor tuning value	
13	4/6	33	Swap D45	For layout	
14	4/9	31	Change R1564 from 33k to 18k	DVT Board ID	
15	4/9	30	Swap JSPK1	For swap speaker cable	
16	4/9	31	Add VSB_ON on GPIO127	For S5 power saving	
17	4/11	29	Change R1527 to R-short	For cost down	
18	4/11	31	Change R1580, R1586 to R-short	For cost down	
19	4/11	13	Change R167 to R-short	For cost down	
20	4/11	31	Change R1591 to always mount	For MainPowerON power control	
21	4/11	7	Change R51, R52 to R-short	For cost down	
22	4/11	12	Change R1610, R1611 to R-short	For cost down	
23	4/11	17	Change R400 to R-short	For cost down	
24	4/11	22	Mount R200, @ L171, C238, C239	For LVDS Translator 1.2 power rail	
25	4/11	26	Change R1515, R1508 to R-short	For cost down	
26	4/11	27	Delete J17, J19	For LAN surge solution change	
27	4/12	5	Change A6, A10 APU R1 PN	From PC sample to PR sample	
28	4/13	17,19	Change BIF_VDDC to VGA_CORE and move C343 to Page 19	For PX5 only	
29	4/16	27	Change CHASSIS2_GND to GND & CHASSIS1_GND	For common LAN surge solution	
30	4/17	33	Mount L43, L44, L45, @ R1605, R1608, R1609, R1612, R1613, R1616	For EMI (USB3.0 choke)	
31	4/17	32	Add L50, L51, L52 @ R1614, R1615, R1619, R1624, R1625, R1626	For EMI (USB2.0 choke from SB to MB)	
32	4/17	30	Change R937, R1548 from 0 ohm to L172, L173 300ohm Bead	For EMI (DMIC DATA , CLK)	
33	4/17	7	Change R26,R28 from 1k to 10k	For APU_SIC, SID 0'C shut down issue workaround	
34	4/18	7	Change back R26,R28 from 10k to 1k, and mount C5988	For APU_SIC, SID 0'C shut down issue	

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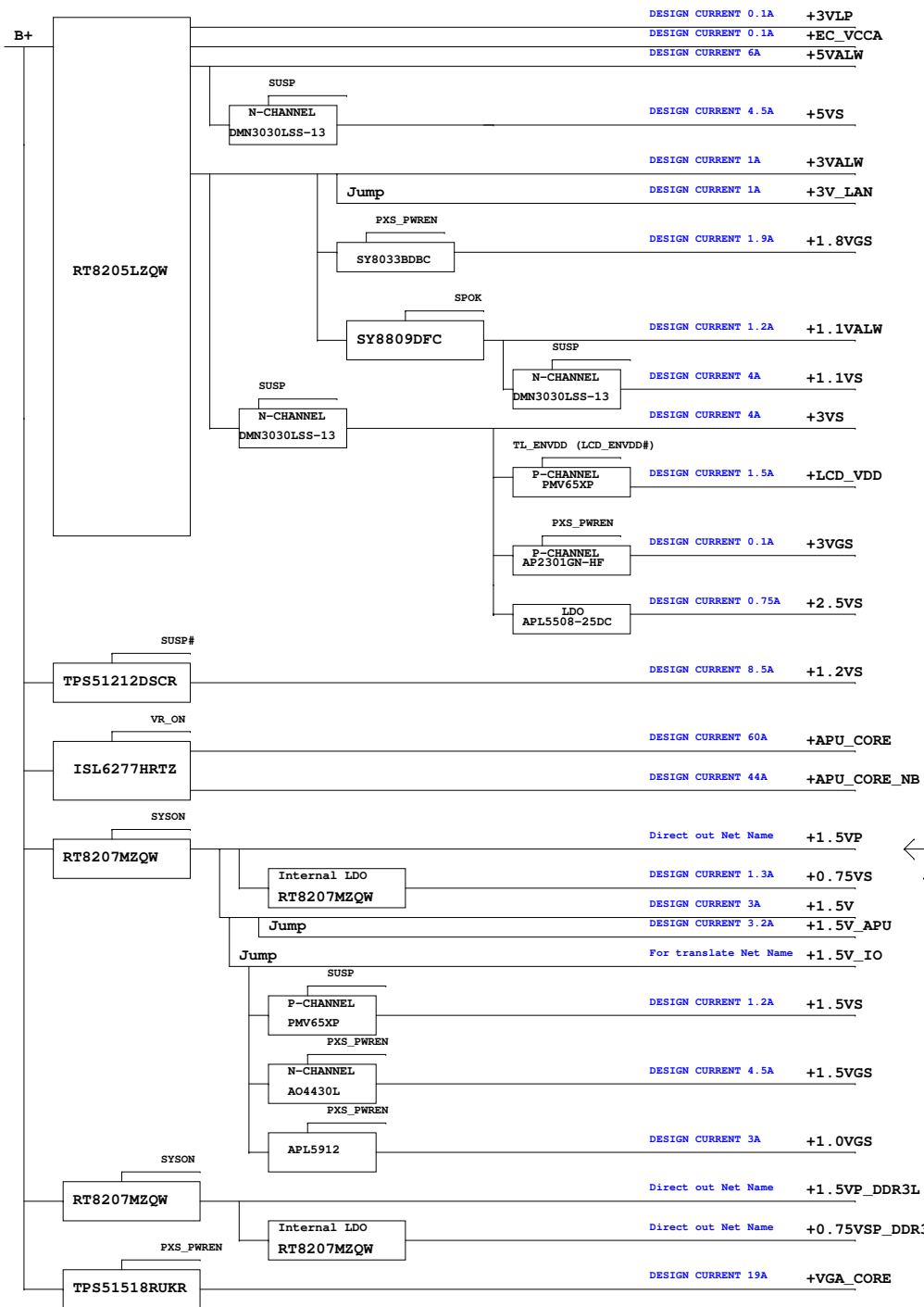
VAUS5 HW PIR List

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NO	DATE	PAGE	MODIFICATION LIST	PURPOSE	NOTE
1	5/11	16	Change Q64 from SB00000E010 to SB00000DH00	For BOM reduce	
2	5/11	23	Reserve R1466	For factory requirement to prevent DISPOFF# damage	
3	5/11	25	Add BOM structure SSD@ for SSD function	For BOM option	
4	5/14	24	Reserve ESD component D1,D2 for HDMI signal	For HDMI hot-plug protection	
5	5/21	7 13 25 26 30	0402 R-Shot modify R24, R160, R161, R158, R163, R171, R169, R166, R1491, R1492 0603 R-Shot modify R157, R164, R170, R172, R168, R159, R1529, L35, L36 0805 R-Shot modify R162, R165, R1531	For BOM reduce	
6	5/21	31	Change R1564 from 18K to 8.2K	For Board ID change	
7	5/22	7	Change back R24 from R-shot to 0ohm		
8	5/22	24	Reserve ESD component D69 for HDMI SMBus	For APU damage when HDMI hot-plug	
9	5/24	25	Reserve R1493	For Intel 2230 WLAN Card Support	
10	5/24	20	Add VRAM Samsung 1G K4W2G1646E-BC11 strap setting	For customer request	
11	5/24	24	Un-mount D1, D2		
12	5/24	12	Change back R1610, R1611 footprint to 0ohm		
13	5/25	30	Add C83, C84 for DMIC noise issue	For EMI request	
14	5/25	27	Change DL2 PN to SCV00001D00	For customer request	
15	5/25	10 25	Add BT_OFF# for other BT combo card	For customer request	
16	5/29	26	Un-mount C1197. C1198 and mount C1200,C1203	For LAN power trace rounting	
17	5/29	7	Change Q3,Q4 PN from SB501110010 to SB501380050	For PUR request	
18	5/29	30	Change R1530 PN from SM01000D100 to SM010005X00	For PUR request	
19	5/31	23 25 32 33	Change C8244,C8245,C8246,C8247,C8248 and C8249 from 10p to 15p	For AMD suggest	







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